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(54) **SIGNAL SPLITTING CARRIER AGGREGATION RECEIVER ARCHITECTURE**

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H04B 1/00 (2006.01)

(52) **U.S. Cl.**
CPC ***H04B 1/3805*** (2013.01); ***H04B 1/005*** (2013.01)

(58) **Field of Classification Search**
USPC 455/313, 323, 73; 375/219, 332; 370/310
See application file for complete search history.

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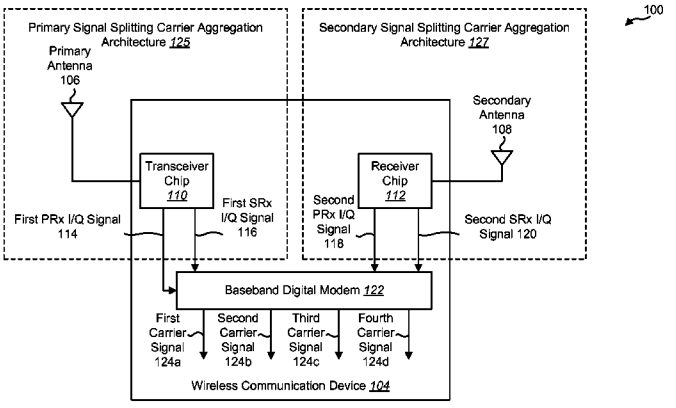
(57) **ABSTRACT**

A wireless communication device configured for receiving a multiple carrier signal is described. The wireless communication device includes a primary signal splitting carrier aggregation architecture. The primary signal splitting carrier aggregation architecture includes a primary antenna and a transceiver chip. The primary signal splitting carrier aggregation architecture reuses a first diversity/simultaneous hybrid dual receiver path. The wireless communication device also includes a secondary signal splitting carrier aggregation architecture. The secondary signal splitting carrier aggregation architecture includes a secondary antenna and a receiver chip. The secondary signal splitting carrier aggregation architecture reuses a second diversity/simultaneous hybrid dual receiver path.

40 Claims, 15 Drawing Sheets



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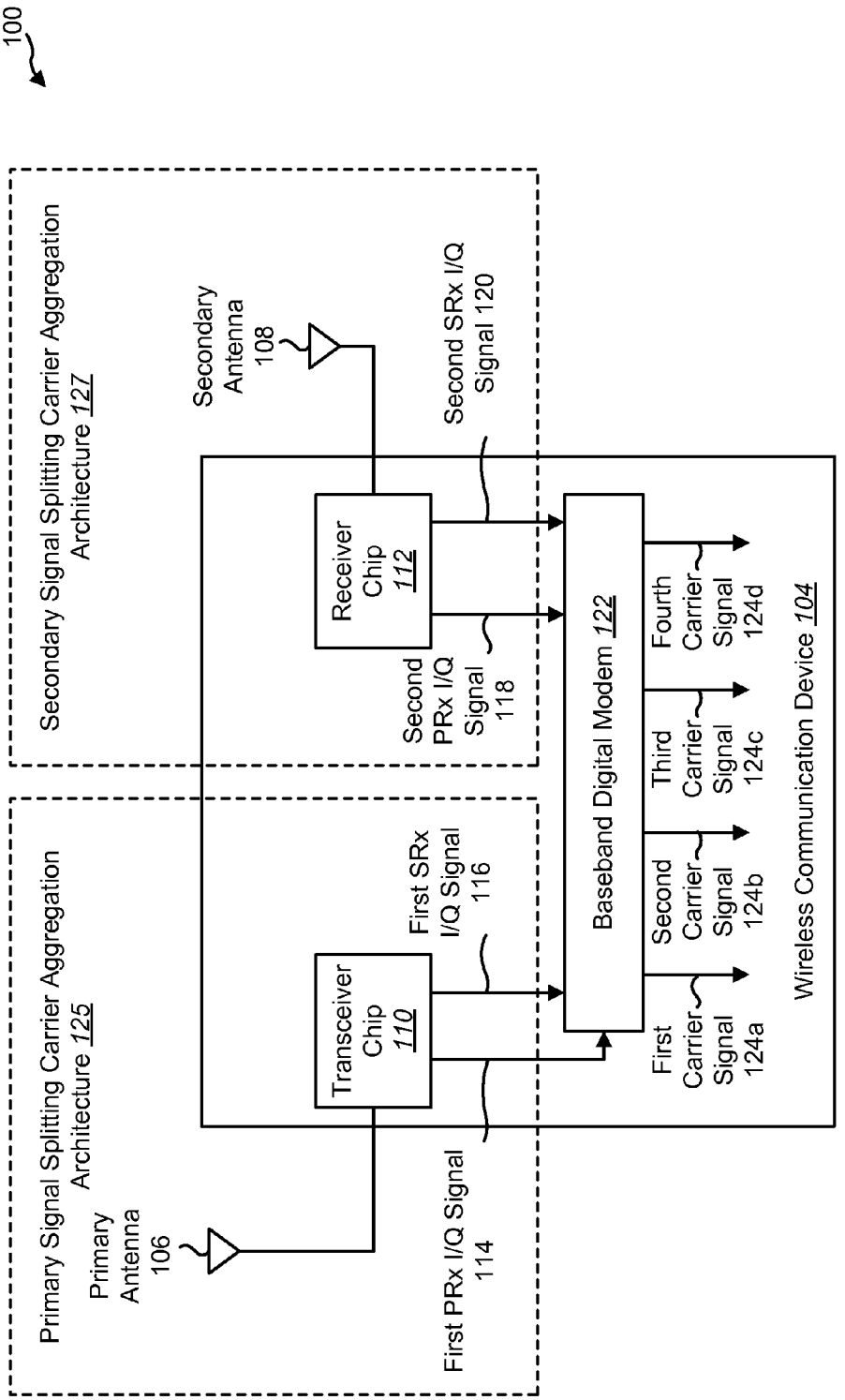
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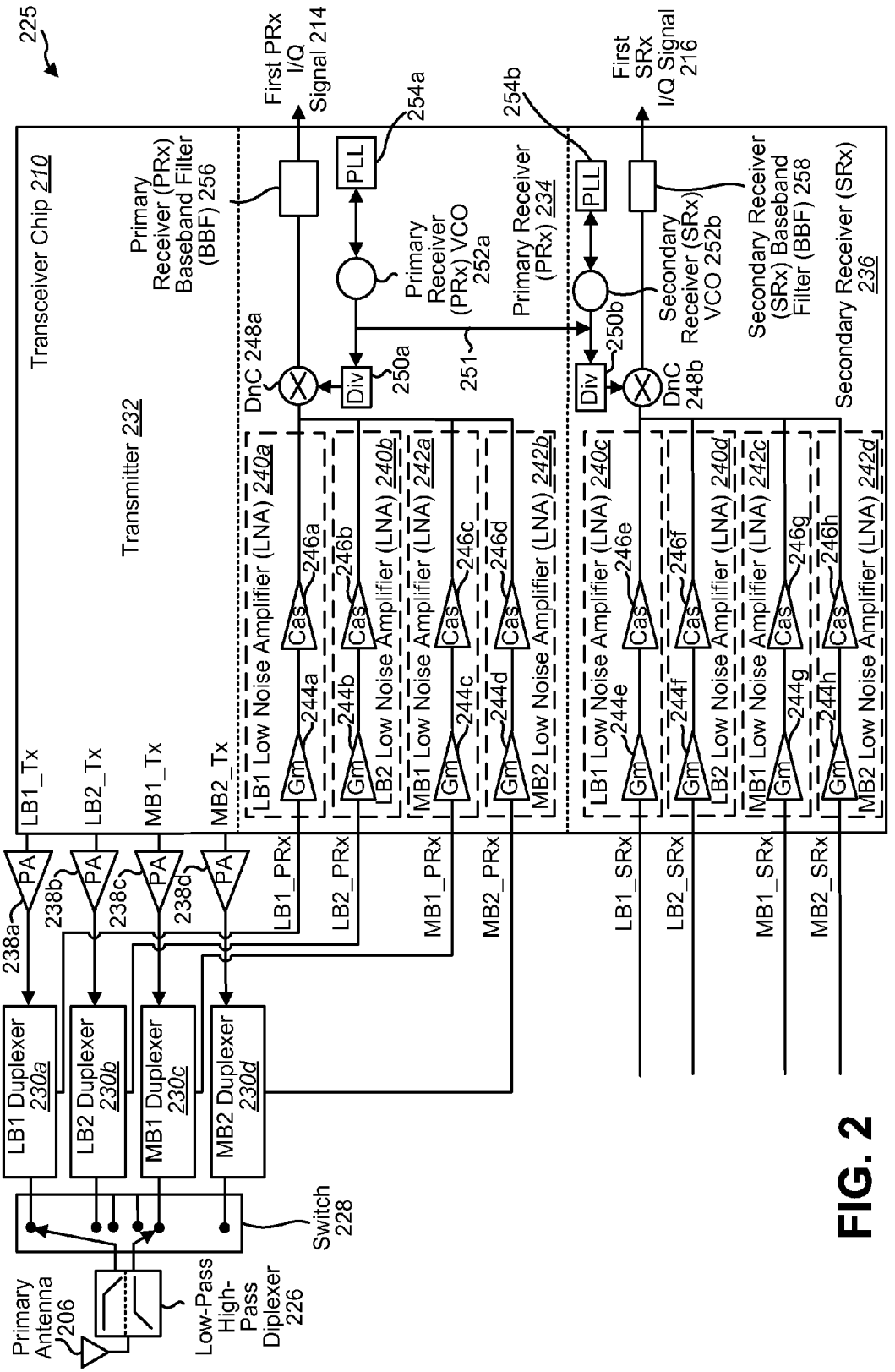
Primary Antenna 106
Transceiver Chip 110
First PRx I/Q Signal 114
First SRx I/Q Signal 116
Secondary Signal Splitting Carrier Aggregation Architecture 127
Secondary Antenna 108
Receiver Chip 112
Second PRx I/Q Signal 118
Second SRx I/Q Signal 120
Baseband Digital Modem 122
First Carrier Signal 124a
Second Carrier Signal 124b
Third Carrier Signal 124c
Fourth Carrier Signal 124d
Wireless Communication Device 104

FIG. 1


225
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Transmitter 232
Primary Receiver (PRx) Baseband Filter (BBF) 256
First PRx I/Q Signal 214
254a
254b
First SRx I/Q Signal 216
PLL
Primary Receiver (PRx) VCO 252a
Primary Receiver (PRx) 234
Secondary Receiver (SRx) VCO 252b
Secondary Receiver (SRx) Baseband Filter (BBF) 258
Secondary Receiver (SRx) 236
DnC 248a
DnC 248b
Div
250a
250b
251
LB1_Tx
LB2_Tx
MB1_Tx
MB2_Tx
PA
238a
238b
238c
238d
LB1 Duplexer 230a
LB2 Duplexer 230b
MB1 Duplexer 230c
MB2 Duplexer 230d
Switch 228
Primary Antenna 206
Low-Pass High-Pass Diplexer 226
LB1_PRx
LB2_PRx
MB1_PRx
MB2_PRx
LB1_SRx
LB2_SRx
MB1_SRx
MB2_SRx
LB1 Low Noise Amplifier (LNA) 240a
LB2 Low Noise Amplifier (LNA) 240b
MB1 Low Noise Amplifier (LNA) 242a
MB2 Low Noise Amplifier (LNA) 242b
LB1 Low Noise Amplifier (LNA) 240c
LB2 Low Noise Amplifier (LNA) 240d
MB1 Low Noise Amplifier (LNA) 242c
MB2 Low Noise Amplifier (LNA) 242d
Gm
Cas
244a
244b
244c
244d
244e
244f
244g
244h
246a
246b
246c
246d
246e
246f
246g
246h

FIG. 2

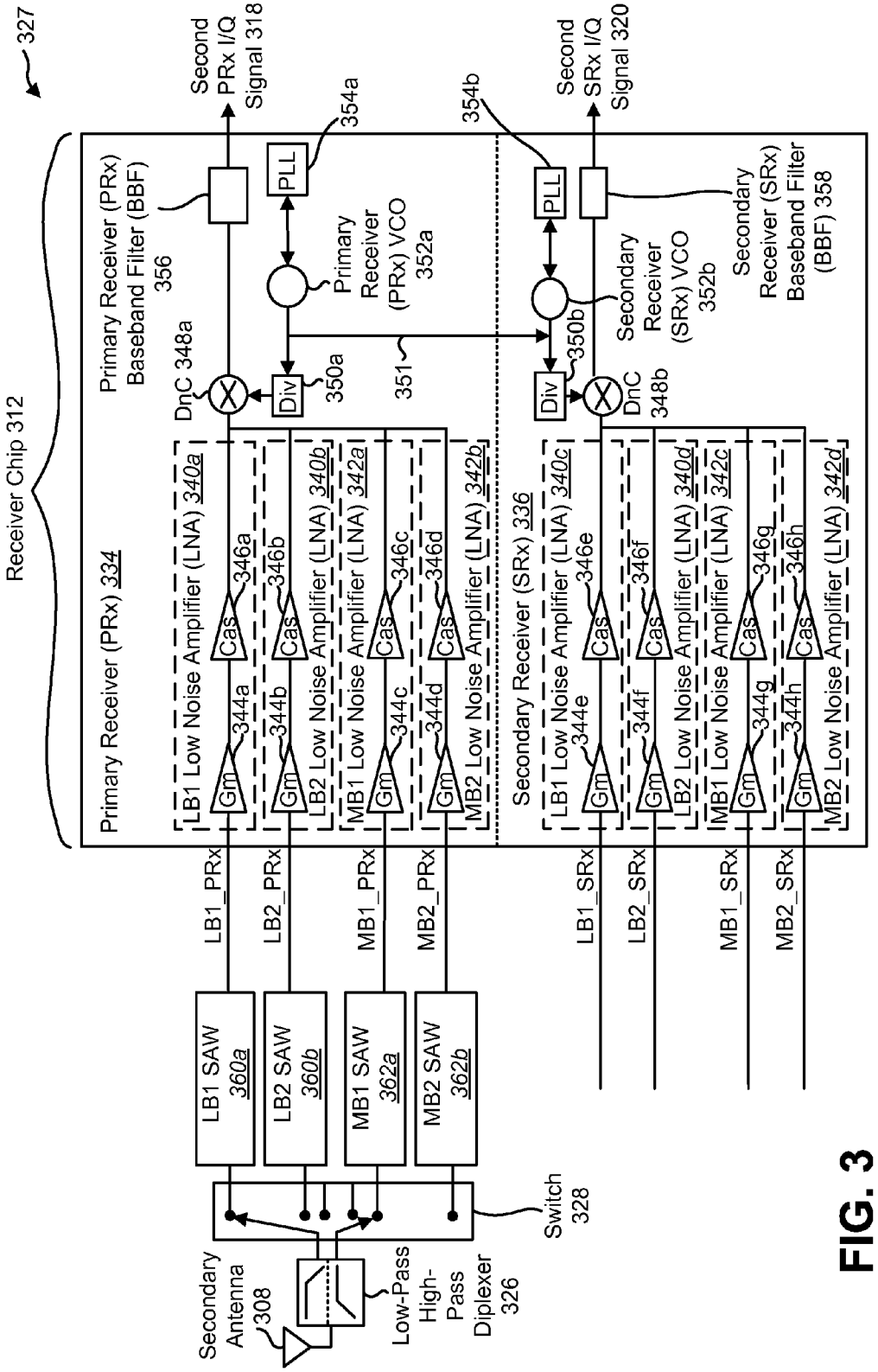
327
Receiver Chip 312
Primary Receiver (PRx) 334
Secondary Receiver (SRx) 336
Second PRx I/Q Signal 318
Second SRx I/Q Signal 320
Primary Receiver Baseband Filter (BBF) 356
Secondary Receiver (SRx) Baseband Filter (BBF) 358
PLL
354a
354b
Primary Receiver (PRx) VCO 352a
Secondary Receiver (SRx) VCO 352b
DnC 348a
DnC 348b
Div
350a
350b
351
LB1 Low Noise Amplifier (LNA) 340a
LB2 Low Noise Amplifier (LNA) 340b
MB1 Low Noise Amplifier (LNA) 342a
MB2 Low Noise Amplifier (LNA) 342b
LB1 Low Noise Amplifier (LNA) 340c
LB2 Low Noise Amplifier (LNA) 340d
MB1 Low Noise Amplifier (LNA) 342c
MB2 Low Noise Amplifier (LNA) 342d
Cas
Gm
346a
346b
346c
346d
346e
346f
346g
346h
344a
344b
344c
344d
344e
344f
344g
344h
LB1_PRx
LB2_PRx
MB1_PRx
MB2_PRx
LB1_SRx
LB2_SRx
MB1_SRx
MB2_SRx
LB1 SAW 360a
LB2 SAW 360b
MB1 SAW 362a
MB2 SAW 362b
Switch 328
Secondary Antenna 308
Low-Pass High-Pass Diplexer 326

FIG. 3

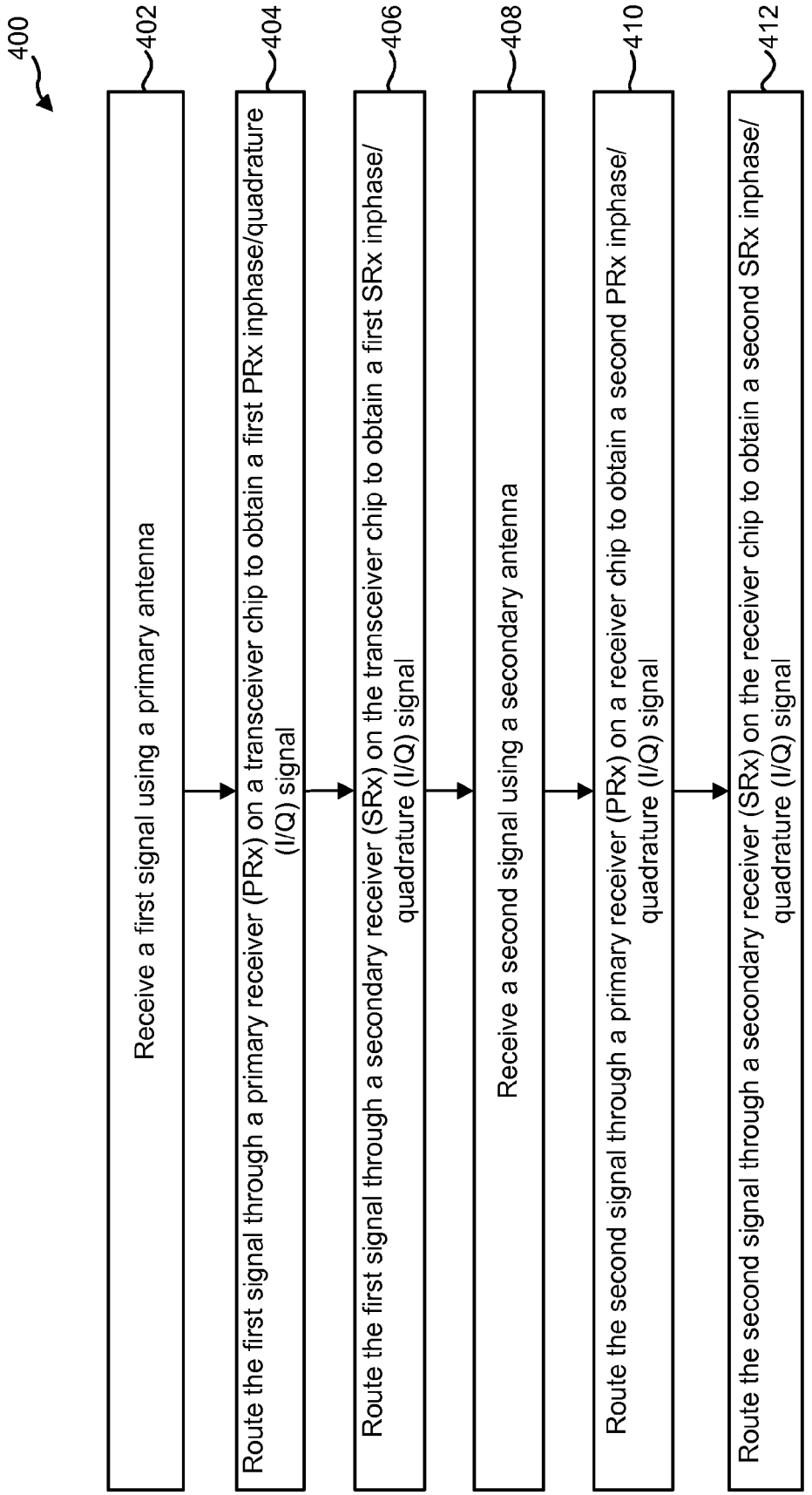
400
402
Receive a first signal using a primary antenna
404
Route the first signal through a primary receiver (PRx) on a transceiver chip to obtain a first PRx inphase/quadrature (I/Q) signal
406
Route the first signal through a secondary receiver (SRx) on the transceiver chip to obtain a first SRx inphase/quadrature (I/Q) signal
408
Receive a second signal using a secondary antenna
410
Route the second signal through a primary receiver (PRx) on a receiver chip to obtain a second PRx inphase/quadrature (I/Q) signal
412
Route the second signal through a secondary receiver (SRx) on the receiver chip to obtain a second SRx inphase/quadrature (I/Q) signal

FIG. 4

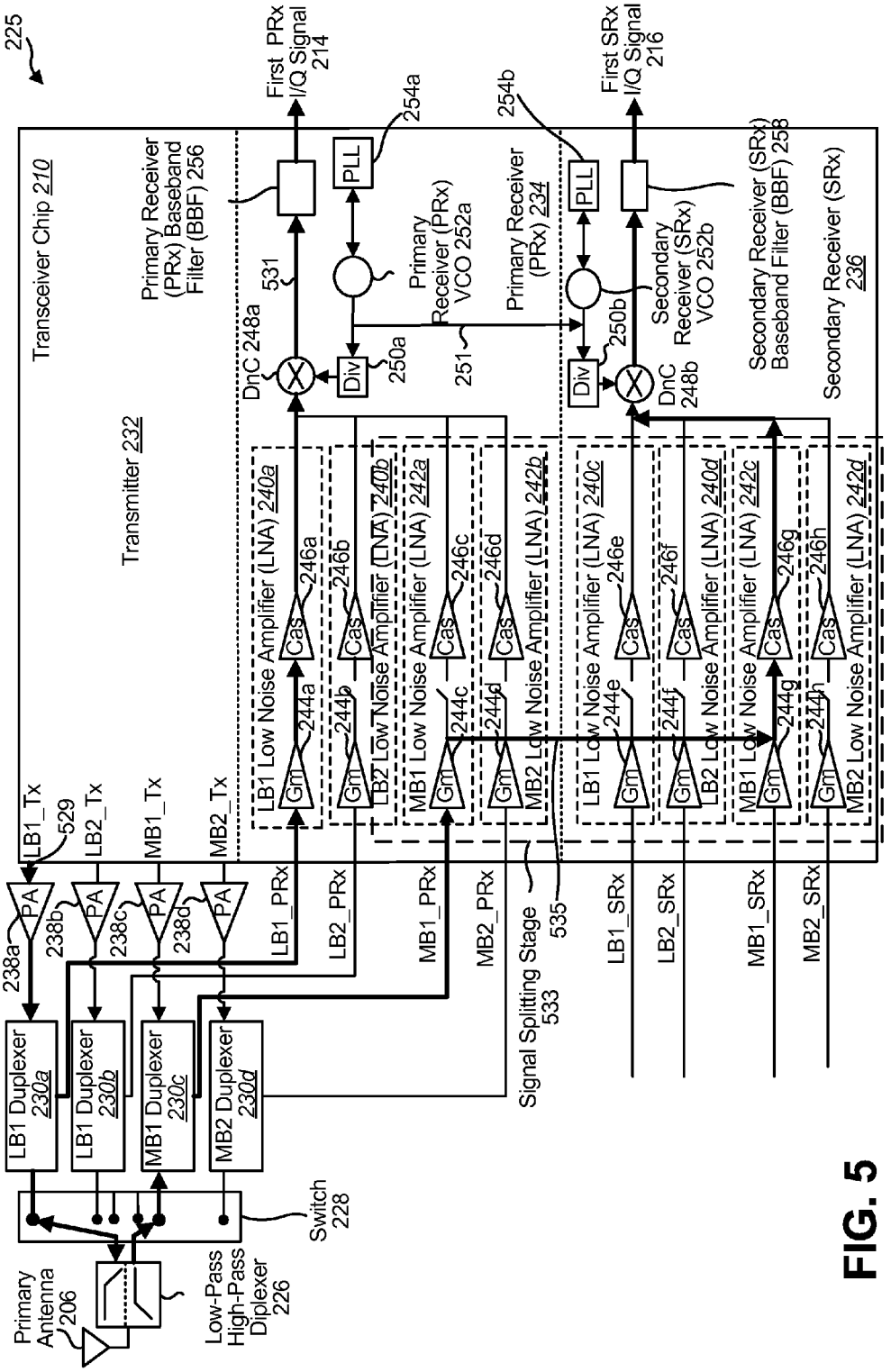
225
Transceiver Chip 210
Transmitter 232
Primary Receiver (PRx) Baseband Filter (BBF) 256
First PRx I/Q Signal 214
First SRx I/Q Signal 216
254a
254b
PLL
Primary Receiver VCO 252a
Secondary Receiver VCO 252b
Primary Receiver (PRx) 234
Secondary Receiver (SRx) 236
Secondary Receiver (SRx) Baseband Filter (BBF) 258
DnC 248a
DnC 248b
531
Div
250a
250b
251
LB1_Tx
LB2_Tx
MB1_Tx
MB2_Tx
529
PA
238a
238b
238c
238d
LB1 Duplexer 230a
LB1 Duplexer 230b
MB1 Duplexer 230c
MB2 Duplexer 230d
Switch 228
Primary Antenna 206
Low-Pass High-Pass Diplexer 226
LB1 Low Noise Amplifier (LNA) 240a
LB2 Low Noise Amplifier (LNA) 240b
MB1 Low Noise Amplifier (LNA) 242a
MB2 Low Noise Amplifier (LNA) 242b
LB1 Low Noise Amplifier (LNA) 240c
LB2 Low Noise Amplifier (LNA) 240d
MB1 Low Noise Amplifier (LNA) 242c
MB2 Low Noise Amplifier (LNA) 242d
Gm
Cas
244a
244b
244c
244d
244e
244f
244g
244h
246a
246b
246c
246d
246e
246f
246g
246h
LB1_PRx
LB2_PRx
MB1_PRx
MB2_PRx
Signal Splitting Stage 533
535
LB1_SRx
LB2_SRx
MB1_SRx
MB2_SRx

FIG. 5

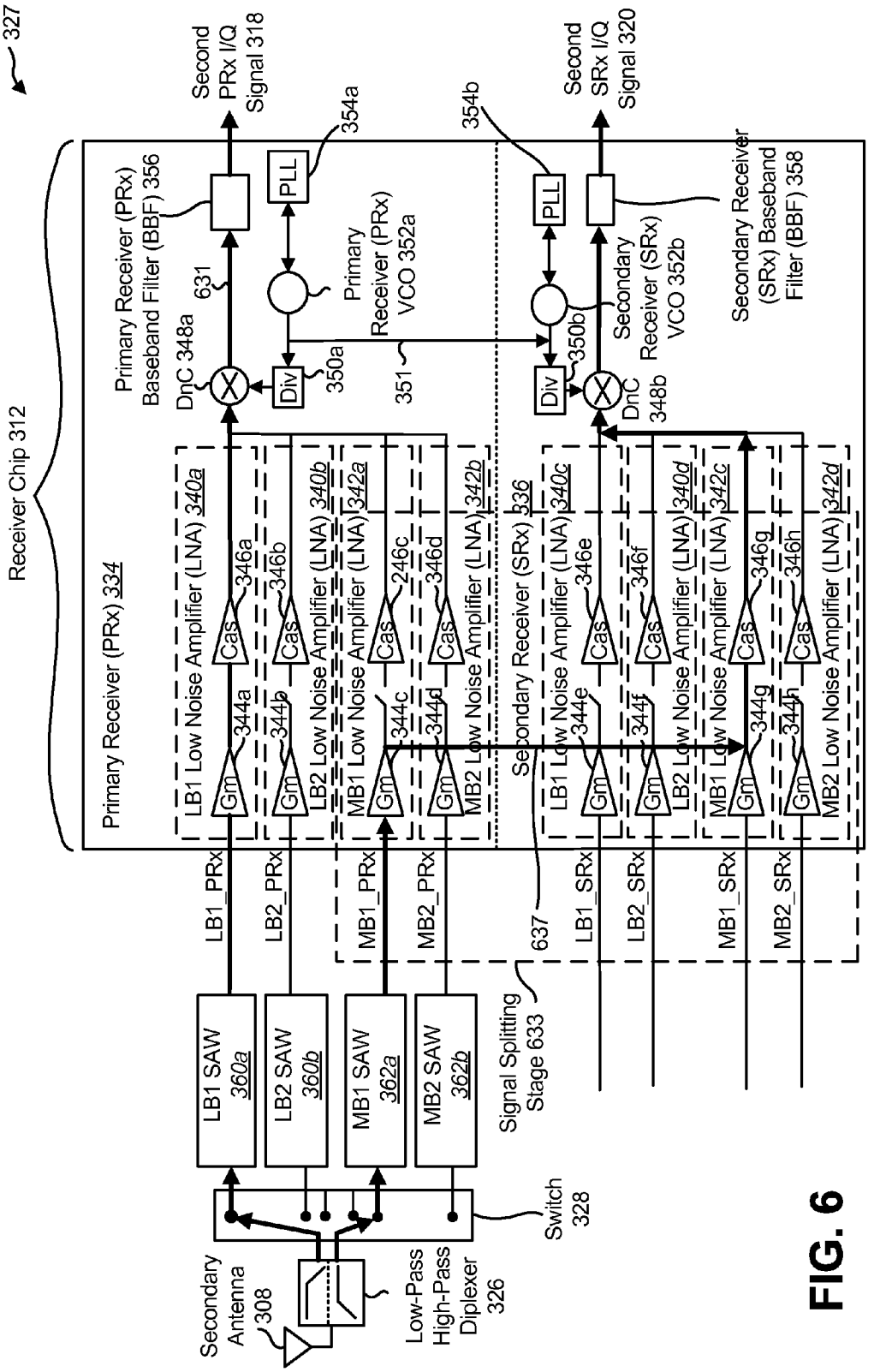
327
Receiver Chip 312
Primary Receiver (PRx) 334
Primary Receiver (PRx) Baseband Filter (BBF) 356
Second PRx I/Q Signal 318
Second SRx I/Q Signal 320
Secondary Receiver (SRx) Baseband Filter (BBF) 358
Secondary Receiver (SRx) 336
PLL
354a
354b
631
DnC 348a
DnC 348b
Div
350a
350b
351
Primary Receiver (PRx) VCO 352a
Secondary Receiver (SRx) VCO 352b
LB1 Low Noise Amplifier (LNA) 340a
LB2 Low Noise Amplifier (LNA) 340b
MB1 Low Noise Amplifier (LNA) 342a
MB2 Low Noise Amplifier (LNA) 342b
LB1 Low Noise Amplifier (LNA) 340c
LB2 Low Noise Amplifier (LNA) 340d
MB1 Low Noise Amplifier (LNA) 342c
MB2 Low Noise Amplifier (LNA) 342d
Cas
Gm
346a
346b
246c
346d
346e
346f
346g
346h
344a
344b
344c
344d
344e
344f
344g
344h
LB1_PRx
LB2_PRx
MB1_PRx
MB2_PRx
LB1_SRx
LB2_SRx
MB1_SRx
MB2_SRx
637
Signal Splitting Stage 633
LB1 SAW 360a
LB2 SAW 360b
MB1 SAW 362a
MB2 SAW 362b
Switch 328
Secondary Antenna 308
Low-Pass High-Pass Diplexer 326

FIG. 6

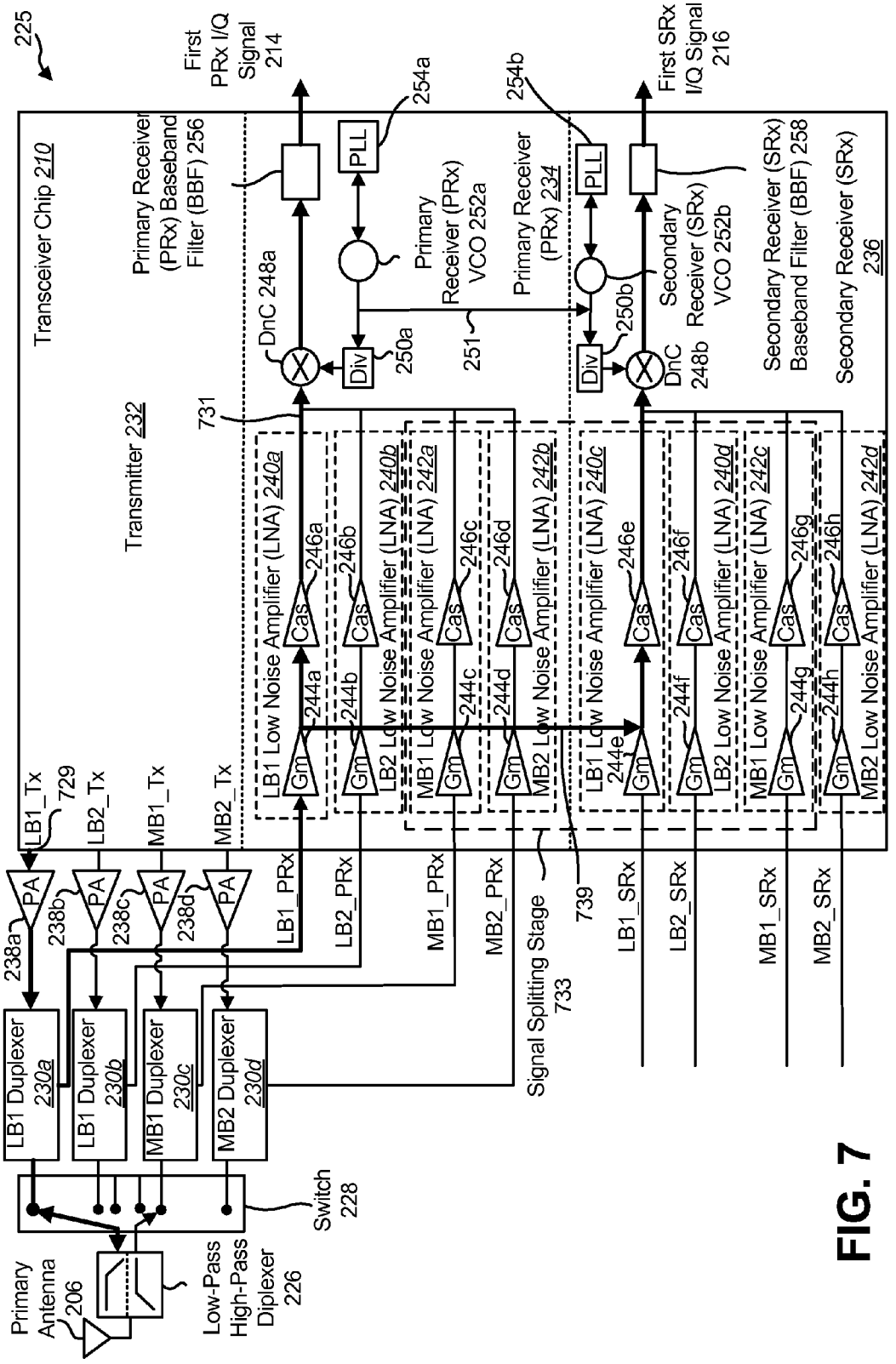
225
Transceiver Chip 210
Transmitter 232
Primary Receiver (PRx) Baseband Filter (BBF) 256
First PRx I/Q Signal 214
First SRx I/Q Signal 216
Secondary Receiver (SRx) Baseband Filter (BBF) 258
Secondary Receiver (SRx) 236
Primary Receiver (PRx) 234
Primary Receiver (PRx) VCO 252a
Secondary Receiver (SRx) VCO 252b
254a
254b
250a
250b
251
731
739
733
DnC 248a
DnC 248b
Div
PLL
LB1_Tx 729
LB2_Tx
MB1_Tx
MB2_Tx
PA
238a
238b
238c
238d
LB1 Duplexer 230a
LB1 Duplexer 230b
MB1 Duplexer 230c
MB2 Duplexer 230d
Switch 228
Primary Antenna 206
Low-Pass High-Pass Diplexer 226
LB1 Low Noise Amplifier (LNA) 240a
LB2 Low Noise Amplifier (LNA) 240b
MB1 Low Noise Amplifier (LNA) 242a
MB2 Low Noise Amplifier (LNA) 242b
LB1 Low Noise Amplifier (LNA) 240c
LB2 Low Noise Amplifier (LNA) 240d
MB1 Low Noise Amplifier (LNA) 242c
MB2 Low Noise Amplifier (LNA) 242d
Gm
Cas
244a
244b
244c
244d
244e
244f
244g
244h
246a
246b
246c
246d
246e
246f
246g
246h
LB1_PRx
LB2_PRx
MB1_PRx
MB2_PRx
LB1_SRx
LB2_SRx
MB1_SRx
MB2_SRx
Signal Splitting Stage

FIG. 7

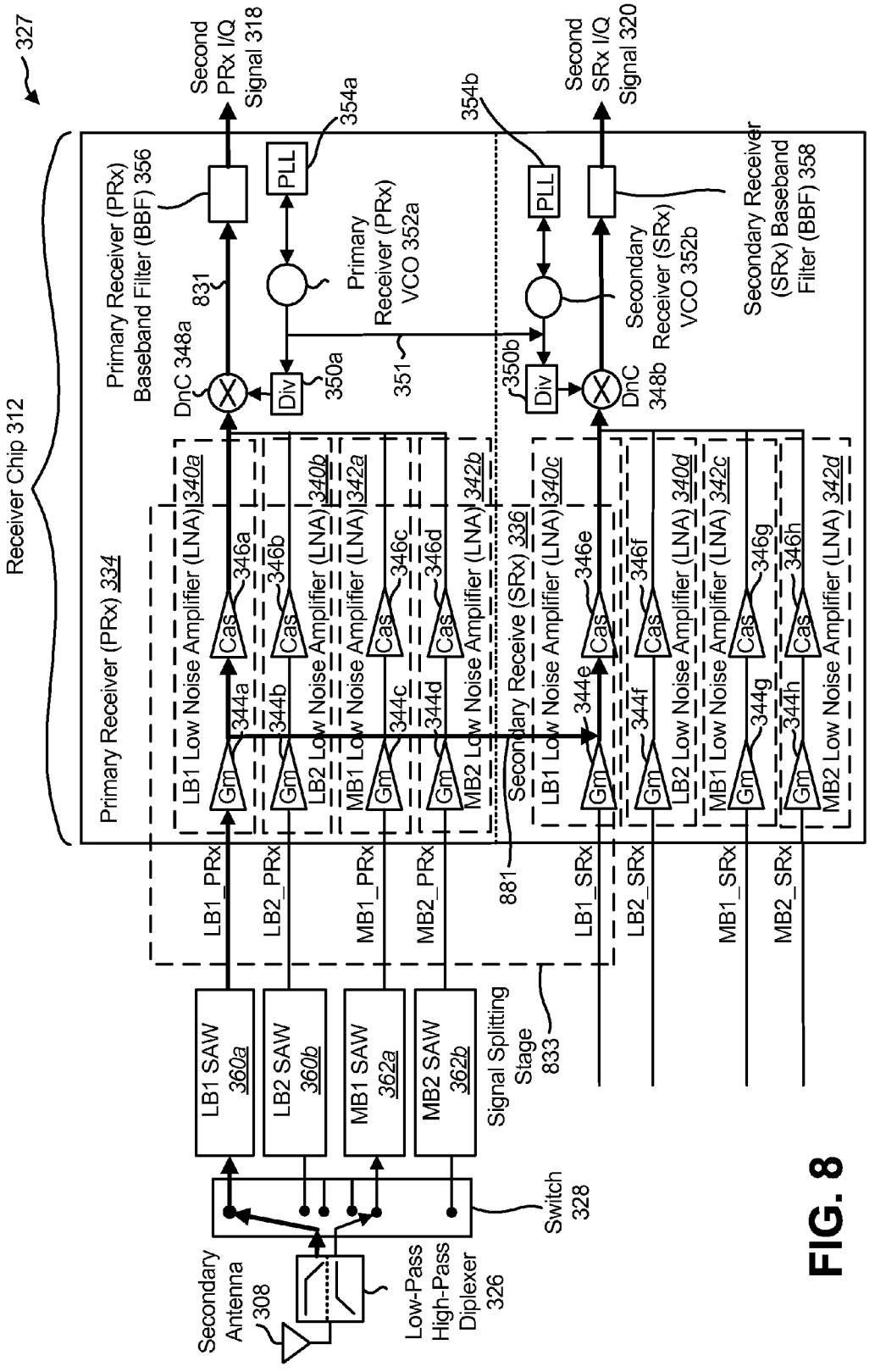
327
Receiver Chip 312
Primary Receiver (PRx) 334
Primary Receiver (PRx) Baseband Filter (BBF) 356
Second PRx I/Q Signal 318
Second SRx I/Q Signal 320
Secondary Receiver (SRx) Baseband Filter (BBF) 358
PLL
354a
354b
Primary Receiver (PRx) VCO 352a
Secondary Receiver (SRx) VCO 352b
831
DnC 348a
DnC 348b
Div
350a
350b
351
LB1 Low Noise Amplifier (LNA) 340a
LB2 Low Noise Amplifier (LNA) 340b
MB1 Low Noise Amplifier (LNA) 342a
MB2 Low Noise Amplifier (LNA) 342b
Secondary Receive (SRx) 336
LB1 Low Noise Amplifier (LNA) 340c
LB2 Low Noise Amplifier (LNA) 340d
MB1 Low Noise Amplifier (LNA) 342c
MB2 Low Noise Amplifier (LNA) 342d
Cas
Gm
346a
346b
346c
346d
346e
346f
346g
346h
344a
344b
344c
344d
344e
344f
344g
344h
LB1_PRx
LB2_PRx
MB1_PRx
MB2_PRx
LB1_SRx
LB2_SRx
MB1_SRx
MB2_SRx
881
LB1 SAW 360a
LB2 SAW 360b
MB1 SAW 362a
MB2 SAW 362b
Signal Splitting Stage 833
Switch 328
Secondary Antenna 308
Low-Pass High-Pass Diplexer 326

FIG. 8

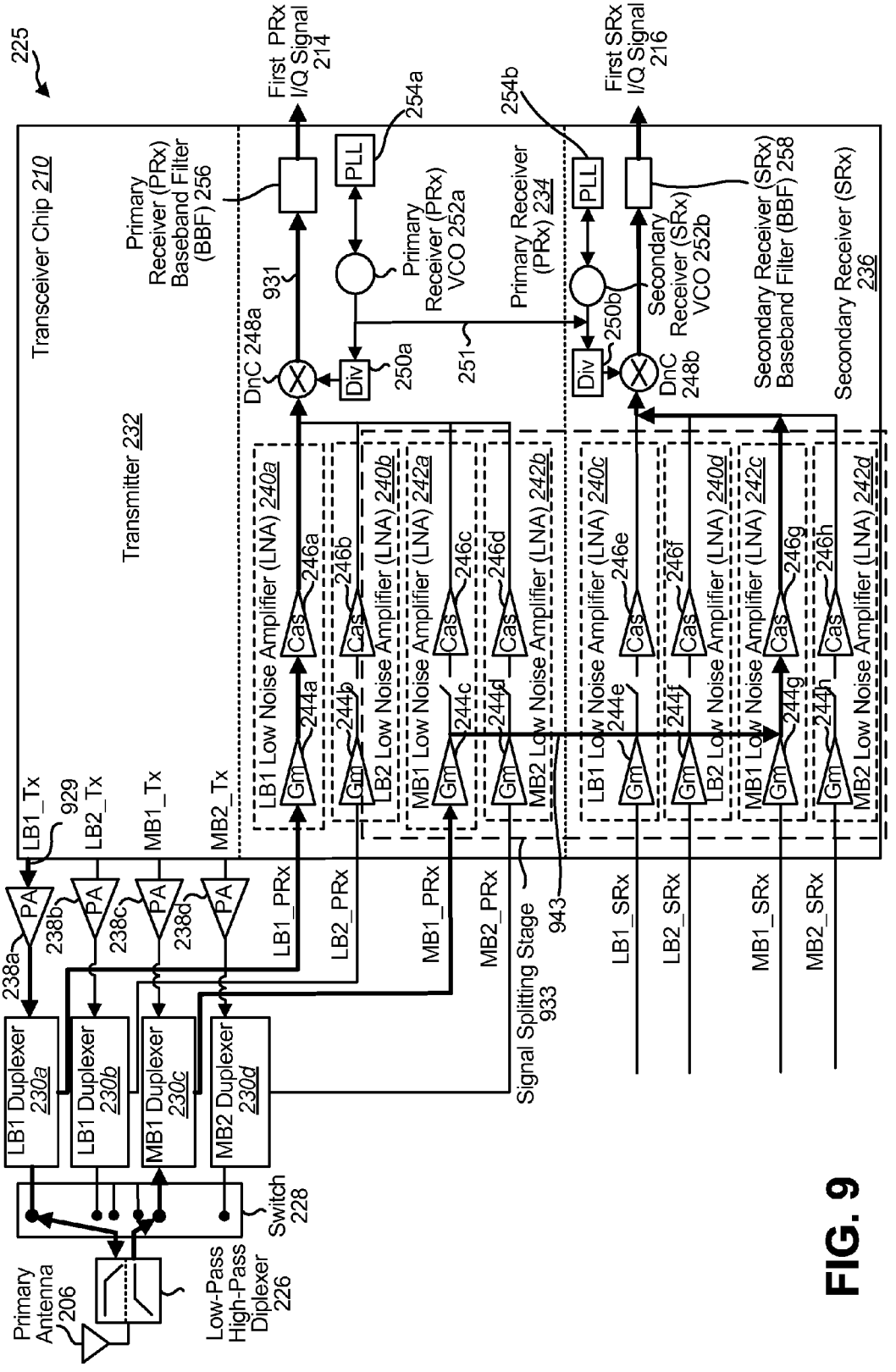
225
Transceiver Chip 210
Transmitter 232
Primary Receiver (PRx) Baseband Filter (BBF) 256
First PRx I/Q Signal 214
First SRx I/Q Signal 216
254a
254b
PLL
Primary Receiver (PRx) VCO 252a
Primary Receiver (PRx) 234
Secondary Receiver (SRx) VCO 252b
Secondary Receiver (SRx) Baseband Filter (BBF) 258
Secondary Receiver (SRx) 236
DnC 248a
DnC 248b
931
Div
250a
250b
251
LB1 Low Noise Amplifier (LNA) 240a
LB2 Low Noise Amplifier (LNA) 240b
MB1 Low Noise Amplifier (LNA) 242a
MB2 Low Noise Amplifier (LNA) 242b
LB1 Low Noise Amplifier (LNA) 240c
LB2 Low Noise Amplifier (LNA) 240d
MB1 Low Noise Amplifier (LNA) 242c
MB2 Low Noise Amplifier (LNA) 242d
Cas
Gm
246a
246b
246c
246d
246e
246f
246g
246h
244a
244b
244c
244d
244e
244f
244g
244h
LB1_Tx
LB2_Tx
MB1_Tx
MB2_Tx
929
PA
238a
238b
238c
238d
LB1 Duplexer 230a
LB1 Duplexer 230b
MB1 Duplexer 230c
MB2 Duplexer 230d
Switch 228
Primary Antenna 206
Low-Pass High-Pass Diplexer 226
LB1_PRx
LB2_PRx
MB1_PRx
MB2_PRx
Signal Splitting Stage 933
943
LB1_SRx
LB2_SRx
MB1_SRx
MB2_SRx

FIG. 9

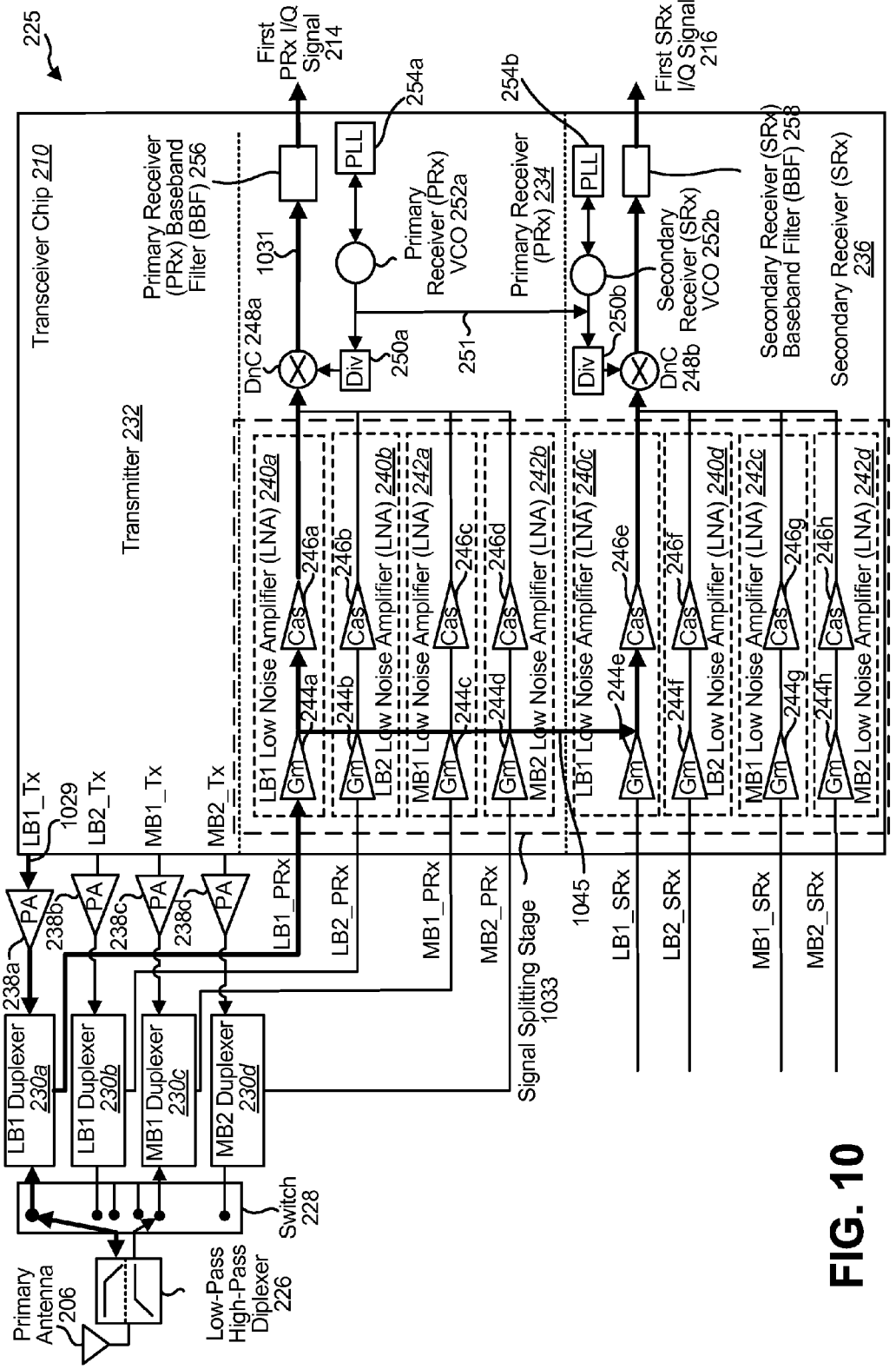
225
Transceiver Chip 210
Transmitter 232
Primary Receiver (PRx) Baseband Filter (BBF) 256
First PRx I/Q Signal 214
First SRx I/Q Signal 216
Primary Receiver (PRx) VCO 252a
Secondary Receiver (SRx) VCO 252b
Primary Receiver (PRx) 234
Secondary Receiver (SRx) Baseband Filter (BBF) 258
Secondary Receiver (SRx) 236
PLL
Div
DnC 248a
DnC 248b
LB1_Tx
LB2_Tx
MB1_Tx
MB2_Tx
PA
LB1 Low Noise Amplifier (LNA) 240a
LB2 Low Noise Amplifier (LNA) 240b
MB1 Low Noise Amplifier (LNA) 242a
MB2 Low Noise Amplifier (LNA) 242b
LB1 Low Noise Amplifier (LNA) 240c
LB2 Low Noise Amplifier (LNA) 240d
MB1 Low Noise Amplifier (LNA) 242c
MB2 Low Noise Amplifier (LNA) 242d
Gm
Cas
LB1_PRx
LB2_PRx
MB1_PRx
MB2_PRx
LB1_SRx
LB2_SRx
MB1_SRx
MB2_SRx
Signal Splitting Stage 1033
LB1 Duplexer 230a
LB1 Duplexer 230b
MB1 Duplexer 230c
MB2 Duplexer 230d
Switch 228
Primary Antenna 206
Low-Pass High-Pass Diplexer 226

FIG. 10

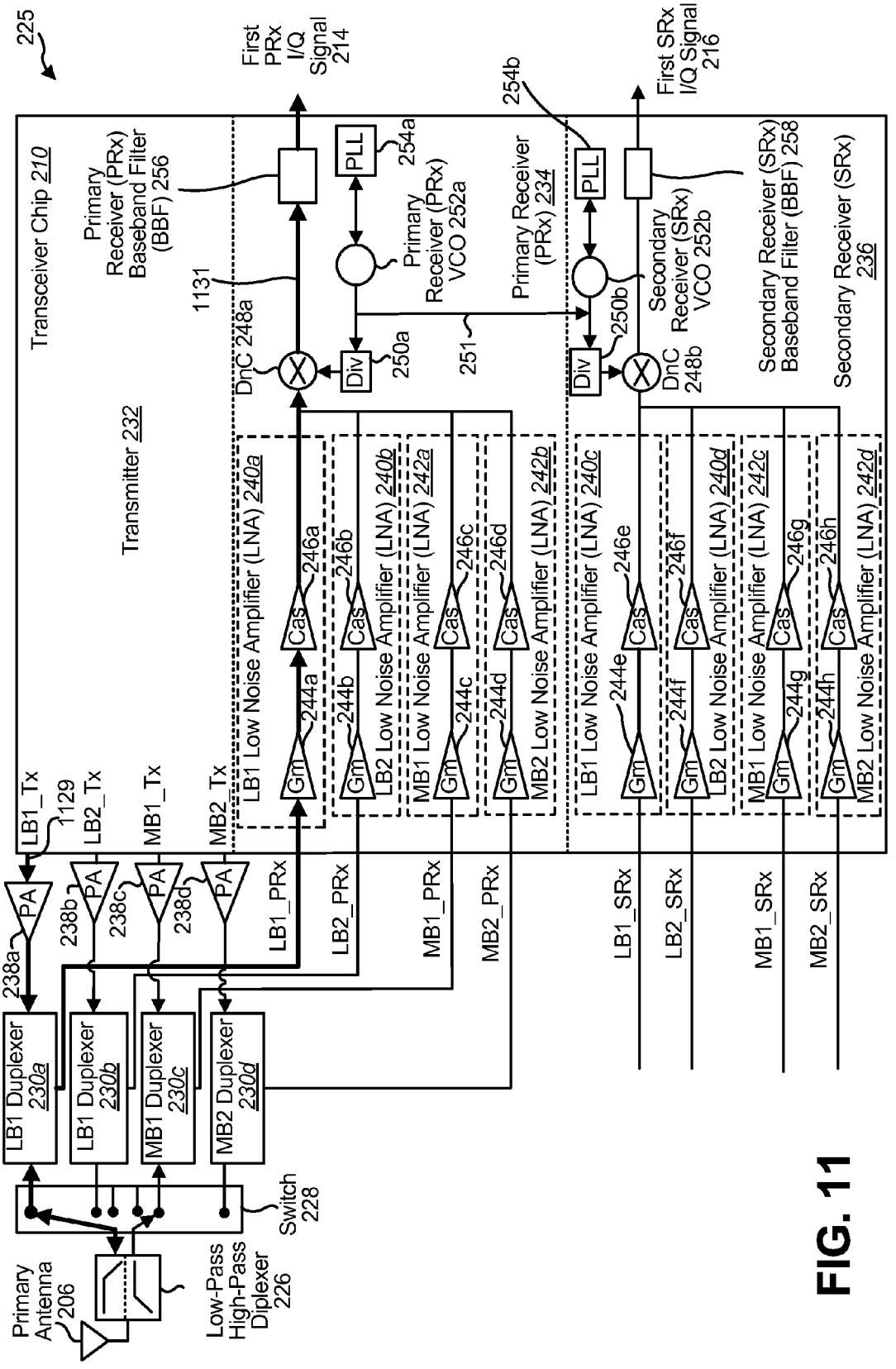
225
Transceiver Chip 210
Transmitter 232
Primary Receiver (PRx) Baseband Filter (BBF) 256
First PRx I/Q Signal 214
First SRx I/Q Signal 216
1131
DnC 248a
Div
250a
PLL
254a
Primary Receiver VCO 252a
251
Primary Receiver (PRx) 234
254b
250b
Secondary Receiver VCO 252b
DnC 248b
Secondary Receiver (SRx) Baseband Filter (BBF) 258
Secondary Receiver (SRx) 236
LB1 Low Noise Amplifier (LNA) 240a
LB2 Low Noise Amplifier (LNA) 240b
MB1 Low Noise Amplifier (LNA) 242a
MB2 Low Noise Amplifier (LNA) 242b
LB1 Low Noise Amplifier (LNA) 240c
LB2 Low Noise Amplifier (LNA) 240d
MB1 Low Noise Amplifier (LNA) 242c
MB2 Low Noise Amplifier (LNA) 242d
Gm
Cas
244a
244b
244c
244d
244e
244f
244g
244h
246a
246b
246c
246d
246e
246f
246g
246h
LB1_Tx
1129
LB2_Tx
MB1_Tx
MB2_Tx
PA
238a
238b
238c
238d
LB1 Duplexer 230a
LB1 Duplexer 230b
MB1 Duplexer 230c
MB2 Duplexer 230d
Switch 228
Low-Pass High-Pass Diplexer 226
Primary Antenna 206
LB1_PRx
LB2_PRx
MB1_PRx
MB2_PRx
LB1_SRx
LB2_SRx
MB1_SRx
MB2_SRx

FIG. 11

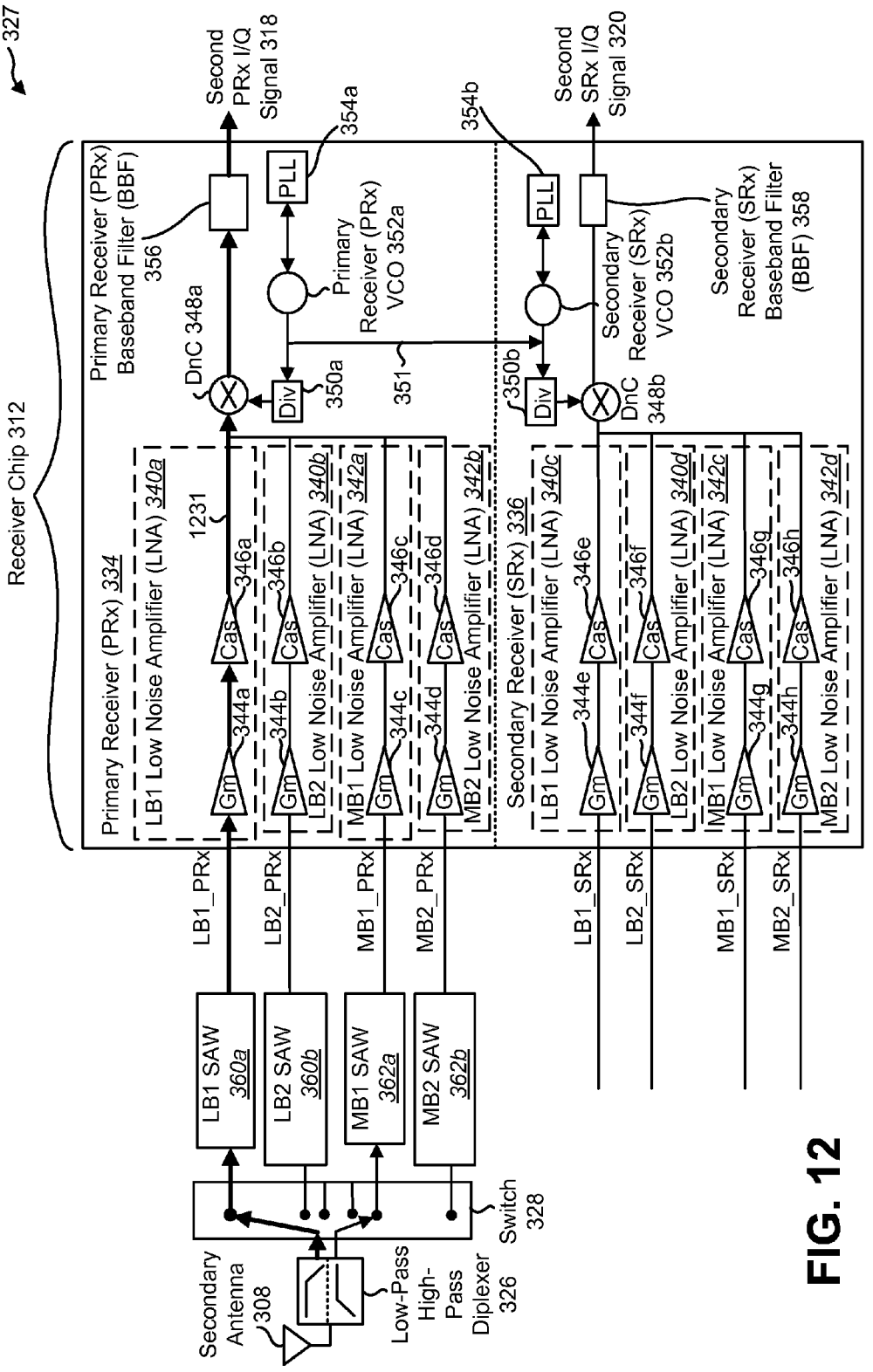
327
Receiver Chip 312
Primary Receiver (PRx) 334
LB1 Low Noise Amplifier (LNA) 340a
Primary Receiver (PRx) Baseband Filter (BBF) 356
Second PRx I/Q Signal 318
DnC 348a
PLL
354a
Primary Receiver (PRx) VCO 352a
Div
350a
351
1231
LB2 Low Noise Amplifier (LNA) 340b
MB1 Low Noise Amplifier (LNA) 342a
MB2 Low Noise Amplifier (LNA) 342b
Secondary Receiver (SRx) 336
LB1 Low Noise Amplifier (LNA) 340c
LB2 Low Noise Amplifier (LNA) 340d
MB1 Low Noise Amplifier (LNA) 342c
MB2 Low Noise Amplifier (LNA) 342d
Cas
Gm
346a
346b
346c
346d
344a
344b
344c
344d
346e
346f
346g
346h
344e
344f
344g
344h
354b
Second SRx I/Q Signal 320
Secondary Receiver (SRx) VCO 352b
Secondary Receiver (SRx) Baseband Filter (BBF) 358
350b
DnC 348b
LB1_PRx
LB2_PRx
MB1_PRx
MB2_PRx
LB1_SRx
LB2_SRx
MB1_SRx
MB2_SRx
LB1 SAW 360a
LB2 SAW 360b
MB1 SAW 362a
MB2 SAW 362b
Switch 328
Secondary Antenna 308
Low-Pass High-Pass Diplexer 326

FIG. 12

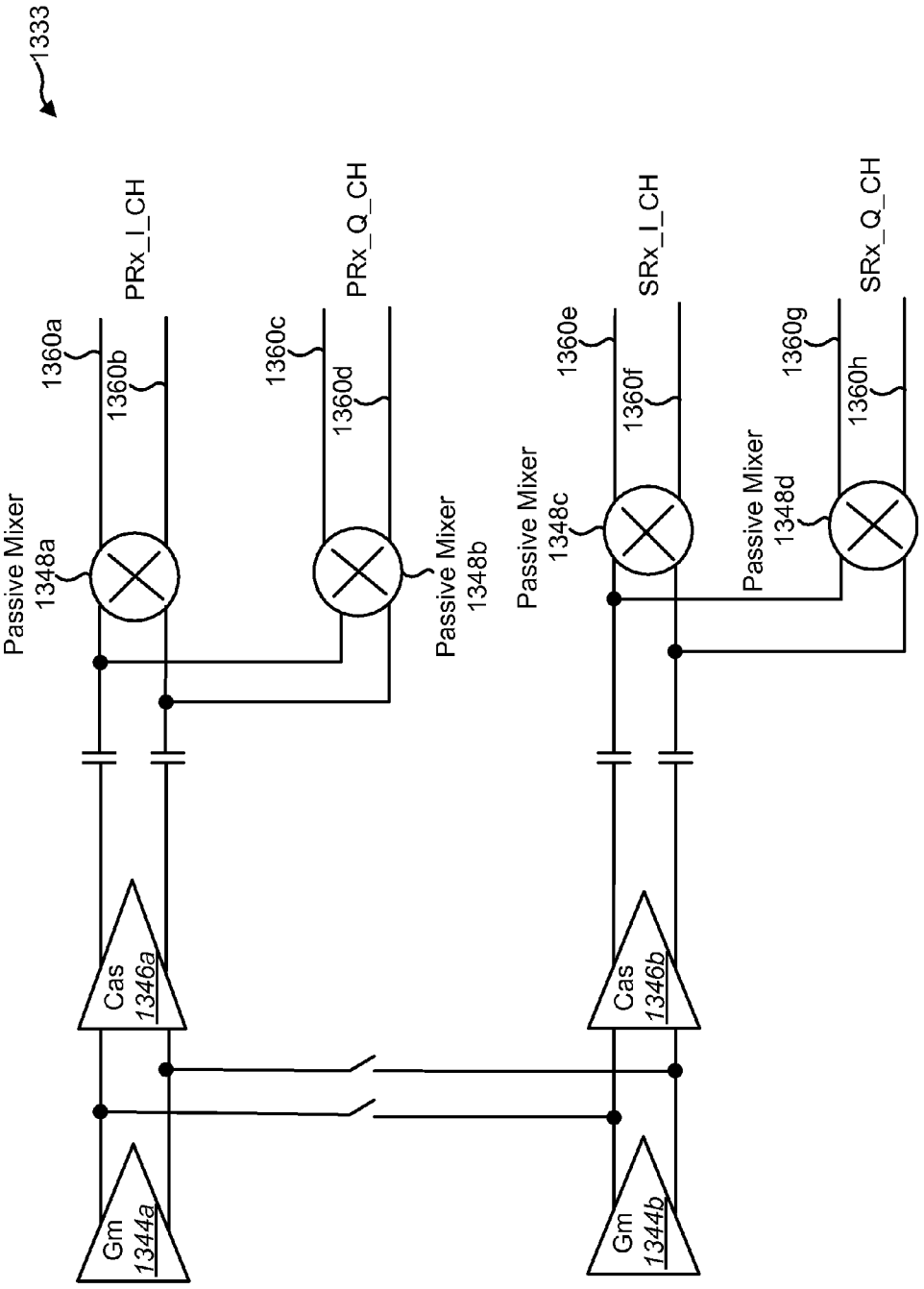
1333
PRx_I_CH
PRx_Q_CH
SRx_I_CH
SRx_Q_CH
1360a
1360b
1360c
1360d
1360e
1360f
1360g
1360h
Passive Mixer
1348a
Passive Mixer
1348b
Passive Mixer
1348c
Passive Mixer
1348d
Cas
1346a
Cas
1346b
Gm
1344a
Gm
1344b

FIG. 13

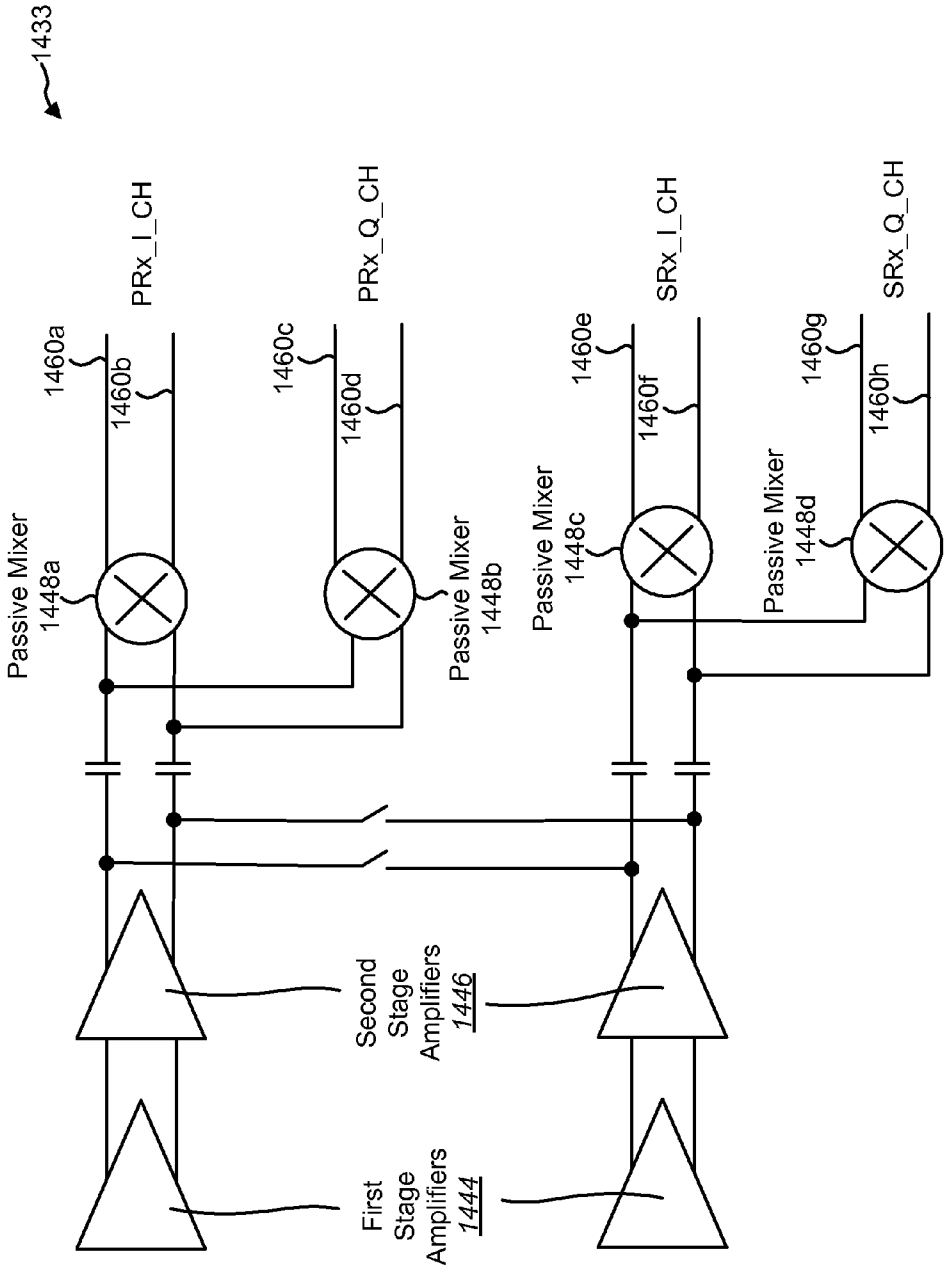
1433
PRx_I_CH
PRx_Q_CH
SRx_I_CH
SRx_Q_CH
1460a
1460b
1460c
1460d
1460e
1460f
1460g
1460h
Passive Mixer 1448a
Passive Mixer 1448b
Passive Mixer 1448c
Passive Mixer 1448d
Second Stage Amplifiers 1446
First Stage Amplifiers 1444

FIG. 14

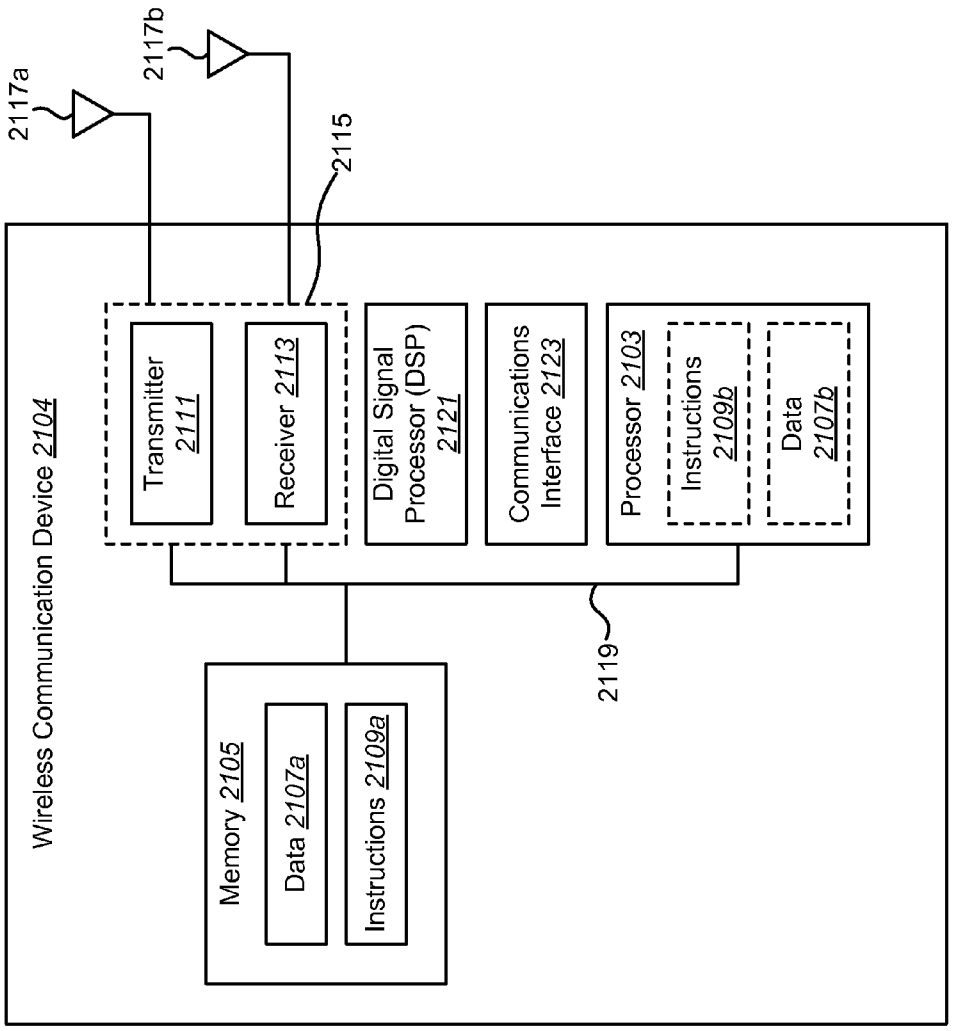
2117a
2117b
2115
Wireless Communication Device 2104
Transmitter 2111
Receiver 2113
Digital Signal Processor (DSP) 2121
Communications Interface 2123
Processor 2103
Instructions 2109b
Data 2107b
Memory 2105
Data 2107a
Instructions 2109a
2119

FIG. 15

SIGNAL SPLITTING CARRIER AGGREGATION RECEIVER ARCHITECTURE

RELATED APPLICATIONS

This application is related to and claims priority from U.S. Provisional Patent Application Ser. No. 61/501,381 filed Jun. 27, 2011, for "CURRENT STEERING CARRIER AGGREGATION RECEIVER ARCHITECTURE."

TECHNICAL FIELD

The present disclosure relates generally to wireless devices for communication systems. More specifically, the present disclosure relates to systems and methods for a signal splitting carrier aggregation receiver architecture.

BACKGROUND

Electronic devices (cellular telephones, wireless modems, computers, digital music players, Global Positioning System units, Personal Digital Assistants, gaming devices, etc.) have become a part of everyday life. Small computing devices are now placed in everything from automobiles to housing locks. The complexity of electronic devices has increased dramatically in the last few years. For example, many electronic devices have one or more processors that help control the device, as well as a number of digital circuits to support the processor and other parts of the device.

These electronic devices may communicate wirelessly with each other and with a network. As the demand for information by these electronic devices has increased, the downlink throughput has also increased. One such way to increase downlink throughput is the use of carrier aggregation. In carrier aggregation, multiple carriers may be aggregated on the physical layer to provide the required bandwidth (and thus the required throughput).

It may be desirable for an electronic device to maximize battery life. Because an electronic device often runs on a battery with a limited operation time, reductions in the power consumption of an electronic device may increase the desirability and functionality of the electronic device.

The electronic devices have also become smaller and cheaper. To facilitate both the decrease in size and the decrease in cost, additional circuitry and more complex circuitry are being used on integrated circuits. Thus, any reduction in the die area used by circuitry may reduce both the size and cost of an electronic device. Benefits may be realized by improvements to electronic devices that allow an electronic device to participate in carrier aggregation while minimizing the cost and size of the electronic device while also minimizing the power consumption of the electronic device.

SUMMARY

A wireless communication device configured for receiving a multiple carrier signal is described. The wireless communication device includes a primary signal splitting carrier aggregation architecture that includes a primary antenna and a transceiver chip. The primary signal splitting carrier aggregation architecture reuses a first diversity/simultaneous hybrid dual receiver path. The wireless communication device also includes a secondary signal splitting carrier aggregation architecture that includes a secondary antenna and a receiver chip. The secondary signal splitting carrier aggregation architecture reuses a second diversity/simultaneous hybrid dual receiver path.

The primary signal splitting carrier aggregation architecture and the secondary signal splitting carrier aggregation architecture may not require four antennas, a power splitter, an external low noise amplifier or die-to-die signal routing. The transceiver chip may include a transmitter, a first primary receiver and a first secondary receiver. The receiver chip may include a second primary receiver and a second secondary receiver. Each receiver may include multiple low noise amplifiers for a first band and multiple low noise amplifiers for a second band. Each low noise amplifier may include a first stage amplifier and a second stage amplifier.

The first stage amplifier may be a transconductance stage and the second stage amplifier may be a cascode stage. In one configuration, the first band may be a low band and the second band may be a mid band. In another configuration, the first band may be a low band and the second band may be a high band. In yet another configuration, the first band may be a mid band and the second band may be a high band.

A first routing may be used from the primary antenna through the first primary receiver to obtain a first primary inphase/quadrature signal. A second routing may be used from the primary antenna through the first secondary receiver to obtain a first secondary inphase/quadrature signal. A third routing may be used from the secondary antenna through the second primary receiver to obtain a second primary inphase/quadrature signal. A fourth routing may be used from the secondary antenna through the second secondary receiver to obtain a second secondary inphase/quadrature signal.

The primary signal splitting carrier aggregation architecture and the secondary signal splitting carrier aggregation architecture may be in inter-band operation. The second routing may pass through a first signal splitting stage. The fourth routing may pass through a second signal splitting stage.

The first signal splitting stage may route a signal output from a first stage amplifier in a first band low noise amplifier of the first primary receiver to a second stage amplifier in a second band low noise amplifier of the first secondary receiver. The second signal splitting stage may route a signal output from a first stage amplifier in a first band low noise amplifier of the second primary receiver to a second stage amplifier in a second band low noise amplifier of the second secondary receiver.

The first signal splitting stage may route a signal output from a second stage amplifier in a first band low noise amplifier of the first primary receiver to a mixer in the first secondary receiver. The second signal splitting stage may route a signal output from a second stage amplifier in a first band low noise amplifier of the second primary receiver to a mixer in the second secondary receiver.

The primary signal splitting carrier aggregation architecture and the secondary signal splitting carrier aggregation architecture may be in intra-band operation. The second routing may pass through a first signal splitting stage. The fourth routing may pass through a second signal splitting stage. The first signal splitting stage may split a signal output from a first stage amplifier in a first band low noise amplifier of the first primary receiver, route the signal to a second stage amplifier in the first band low noise amplifier of the first primary receiver and route the signal to a second stage amplifier in a second band low noise amplifier of the first secondary receiver. The second signal splitting stage may split a signal output from a first stage amplifier in a first band low noise amplifier of the second primary receiver, route the signal to a second stage amplifier in the first band low noise amplifier of

the second primary receiver and route the signal to a second stage amplifier in a second band low noise amplifier of the second secondary receiver.

The first signal splitting stage may split a signal output from a second stage amplifier in a first band low noise amplifier of the first primary receiver, route the signal to a first mixer of the first primary receiver and route the signal to a second mixer of the second primary receiver. The second signal splitting stage may split a signal output from a second stage amplifier in a first band low noise amplifier of the second primary receiver, route the signal to a first mixer of the second primary receiver and route the signal to a second mixer of the second primary receiver.

A method for receiving a multiple carrier signal using a primary signal splitting carrier aggregation architecture and a secondary signal splitting carrier aggregation architecture is also described. A first signal is received using a primary antenna. The first signal is routed through a first primary receiver on a transceiver chip in the primary signal splitting carrier aggregation architecture to obtain a first primary inphase/quadrature signal. The first signal is routed through a first secondary receiver on the transceiver chip to obtain a first secondary inphase/quadrature signal. A second signal is received using a secondary antenna. The second signal is routed through a second primary receiver on a receiver chip in the secondary signal splitting carrier aggregation architecture to obtain a second primary inphase/quadrature signal. The first signal is routed through a second secondary receiver on the receiver chip to obtain a second secondary inphase/quadrature signal.

An apparatus for receiving a multiple carrier signal using a primary signal splitting carrier aggregation architecture and a secondary signal splitting carrier aggregation architecture is described. The apparatus includes means for receiving a first signal using a primary antenna. The apparatus also includes means for routing the first signal through a first primary receiver on a transceiver chip in the primary signal splitting carrier aggregation architecture to obtain a first primary inphase/quadrature signal. The apparatus further includes means for routing the first signal through a first secondary receiver on the transceiver chip to obtain a first secondary inphase/quadrature signal. The apparatus also includes means for receiving a second signal using a secondary antenna. The apparatus further includes means for routing the second signal through a second primary receiver on a receiver chip in the secondary signal splitting carrier aggregation architecture to obtain a second primary inphase/quadrature signal. The apparatus also includes means for routing the first signal through a second secondary receiver on the receiver chip to obtain a second secondary inphase/quadrature signal.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. **1** shows a wireless communication device for use in the present systems and methods;

FIG. **2** is a block diagram illustrating a primary signal splitting carrier aggregation architecture;

FIG. **3** is a block diagram illustrating a secondary signal splitting carrier aggregation architecture;

FIG. **4** is a flow diagram of a method for receiving signals using a signal splitting carrier aggregation architecture;

FIG. **5** is a block diagram illustrating a primary signal splitting carrier aggregation architecture in inter-band operation;

FIG. **6** is a block diagram illustrating a secondary signal splitting carrier aggregation architecture in inter-band operation;

FIG. **7** is a block diagram illustrating a primary signal splitting carrier aggregation architecture in intra-band operation;

FIG. **8** is a block diagram illustrating a secondary signal splitting carrier aggregation architecture in intra-band operation;

FIG. **9** is a block diagram illustrating a primary signal splitting carrier aggregation architecture operating in inter-band simultaneous hybrid dual receiver (SHDR) mode;

FIG. **10** is a block diagram illustrating a primary signal splitting carrier aggregation architecture operating in intra-band simultaneous hybrid dual receiver (SHDR) mode;

FIG. **11** is a block diagram illustrating a primary signal splitting carrier aggregation architecture operating in diversity mode;

FIG. **12** is a block diagram illustrating a secondary signal splitting carrier aggregation architecture operating in diversity mode;

FIG. **13** is a block diagram illustrating a signal splitting stage;

FIG. **14** is a block diagram illustrating another signal splitting stage; and

FIG. **15** illustrates certain components that may be included within a wireless communication device.

DETAILED DESCRIPTION

The 3rd Generation Partnership Project (3GPP) is a collaboration between groups of telecommunications associations that aims to define a globally applicable 3rd generation (3G) mobile phone specification. 3GPP Long Term Evolution (LTE) is a 3GPP project aimed at improving the Universal Mobile Telecommunications System (UMTS) mobile phone standard. The 3GPP may define specifications for the next generation of mobile networks, mobile systems and mobile devices. In 3GPP LTE, a mobile station or device may be referred to as a "user equipment" (UE).

3GPP specifications are based on evolved Global System for Mobile Communications (GSM) specifications, which are generally known as the Universal Mobile Telecommunications System (UMTS). 3GPP standards are structured as releases. Discussion of 3GPP thus frequently refers to the functionality in one release or another. For example, Release 99 specifies the first UMTS third generation (3G) networks, incorporating a CDMA air interface. Release 6 integrates operation with wireless local area networks (LAN) networks and adds High Speed Uplink Packet Access (HSUPA). Release 8 introduces dual downlink carriers and Release 9 extends dual carrier operation to uplink for UMTS.

CDMA2000 is a family of 3rd generation (3G) technology standards that use code division multiple access (CDMA) to send voice, data and signaling between wireless devices. CDMA2000 may include CDMA2000 1X, CDMA2000 EV-DO Rev. 0, CDMA2000 EV-DO Rev. A and CDMA2000 EV-DO Rev. B. 1x or 1xRTT refers to the core CDMA2000 wireless air interface standard. 1x more specifically refers to 1 times Radio Transmission Technology and indicates the same radio frequency (RF) bandwidth as used in IS-95. 1xRTT adds 64 additional traffic channels to the forward link. EV-DO refers to Evolution-Data Optimized. EV-DO is a telecommunications standard for the wireless transmission of data through radio signals.

FIG. **1** shows a wireless communication device **104** for use in the present systems and methods. A wireless communication device **104** may also be referred to as, and may include some or all of the functionality of, a terminal, an access terminal, a user equipment (UE), a subscriber unit, a station,

etc. A wireless communication device **104** may be a cellular phone, a personal digital assistant (PDA), a wireless device, a wireless modem, a handheld device, a laptop computer, a PC card, compact flash, an external or internal modem, a wireline phone, etc. A wireless communication device **104** may be mobile or stationary. A wireless communication device **104** may communicate with zero, one or multiple base stations on a downlink and/or an uplink at any given moment. The downlink (or forward link) refers to the communication link from a base station to a wireless communication device **104**, and the uplink (or reverse link) refers to the communication link from a wireless communication device **104** to a base station. Uplink and downlink may refer to the communication link or to the carriers used for the communication link.

A wireless communication device **104** may operate in a wireless communication system **100** that includes other wireless devices, such as base stations. A base station is a station that communicates with one or more wireless communication devices **104**. A base station may also be referred to as, and may include some or all of the functionality of, an access point, a broadcast transmitter, a Node B, an evolved Node B, etc. Each base station provides communication coverage for a particular geographic area. A base station may provide communication coverage for one or more wireless communication devices **104**. The term "cell" can refer to a base station and/or its coverage area, depending on the context in which the term is used.

Communications in a wireless communication system **100** (e.g., a multiple-access system) may be achieved through transmissions over a wireless link. Such a communication link may be established via a single-input and single-output (SISO) or a multiple-input and multiple-output (MIMO) system. A multiple-input and multiple-output (MIMO) system includes transmitter(s) and receiver(s) equipped, respectively, with multiple (NT) transmit antennas and multiple (NR) receive antennas for data transmission. SISO systems are particular instances of a multiple-input and multiple-output (MIMO) system. The multiple-input and multiple-output (MIMO) system can provide improved performance (e.g., higher throughput, greater capacity or improved reliability) if the additional dimensionalities created by the multiple transmit and receive antennas are utilized.

The wireless communication system **100** may utilize both single-input and multiple-output (SIMO) and multiple-input and multiple-output (MIMO). The wireless communication system **100** may be a multiple-access system capable of supporting communication with multiple wireless communication devices **104** by sharing the available system resources (e.g., bandwidth and transmit power). Examples of such multiple-access systems include code division multiple access (CDMA) systems, wideband code division multiple access (W-CDMA) systems, time division multiple access (TDMA) systems, frequency division multiple access (FDMA) systems, orthogonal frequency division multiple access (OFDMA) systems, single-carrier frequency division multiple access (SC-FDMA) systems, 3rd Generation Partnership Project (3GPP) Long Term Evolution (LTE) systems and spatial division multiple access (SDMA) systems.

The wireless communication device **104** may utilize signal splitting. In signal splitting, signals are directed to a specific path. One form of signal splitting is current steering. In one configuration of intra-band carrier aggregation, signal splitting refers to taking a signal from the output of a first stage amplifier (such as a transconductance stage (Gm)), splitting the signal and piping the signal into two separate primary and secondary stage amplifiers (such as cascode stages (Cas)) and subsequent primary and diversity mixers for carrier aggregation. In another configuration of intra-band carrier aggregation, signal splitting refers to taking a signal from the output of a second stage amplifier (such as a cascode stage (Cas)), splitting the signal and piping the signal into two separate primary and diversity mixers for carrier aggregation.

In one configuration of inter-band carrier aggregation, signal splitting refers to taking a signal output from a first stage amplifier (such as a transconductance stage (Gm)) and steering (or diverting or pumping) the signal into a second stage amplifier (such as a cascode stage (Cas)) and subsequent mixer in the diversity path to be downconverted using a diversity local oscillator (LO). In another configuration of inter-band carrier aggregation, signal splitting refers to taking a signal output from a second stage amplifier (such as a cascode stage (Cas)) and steering (or diverting or pumping) the signal into a subsequent mixer in the diversity path to be downconverted using a diversity local oscillator (LO). The signal steering herein is current steering.

However, voltage steering may also be used. In one configuration of voltage steering for inter-band carrier aggregation, a signal output from a first stage amplifier (such as a transconductance stage (Gm)) may be diverted to a second stage amplifier (such as a cascode stage (Cas)) and subsequent mixer in the diversity path to be downconverted using a diversity local oscillator (LO). In another configuration of voltage steering for inter-band carrier aggregation, a signal output from a second stage amplifier (such as a cascode stage (Cas)) may be diverted to a subsequent mixer in the diversity path to be downconverted using a diversity local oscillator (LO).

The wireless communication device **104** may include a primary antenna **106** and a secondary antenna **108**. The secondary antenna **108** may be referred to as the diversity antenna. A transceiver chip **110** may be coupled to the primary antenna **106**. The transceiver chip **110** may include a transmitter, a primary receiver (PRx) and a secondary receiver (SRx). The transceiver chip **110** may output a first PRx inphase/quadrature (I/Q) signal **114** and a first SRx inphase/quadrature (I/Q) signal **116** to a baseband digital modem **122**. The configuration of the primary antenna **106** and the transceiver chip **110** may be referred to as a primary signal splitting carrier aggregation architecture **125**. The primary signal splitting carrier aggregation architecture **125** is discussed in additional detail below in relation to FIG. **2**.

In general, the primary signal splitting carrier aggregation architecture **125** may split the received signal into the first PRx inphase/quadrature (I/Q) signal **114** using a low noise amplifier (LNA) in the primary receiver (PRx) and the first SRx inphase/quadrature (I/Q) signal **116** using a routing between a first low noise amplifier (LNA) in the primary receiver (PRx) and a second low noise amplifier (LNA) in the secondary receiver (SRx) of the transceiver chip **110**. The routing may couple the output of a stage in the first low noise amplifier (LNA) to the input of a stage in the second low noise amplifier (LNA). There may be many different ways to split the signals. In one configuration, the stage in the first low noise amplifier (LNA) may be a transconductance stage (Gm) and the stage in the second low noise amplifier (LNA) may be a cascode stage (Cas). In another configuration, the first stage may be a transconductance stage (Gm) and the second stage may be a transformer used to split the signal.

A receiver chip **112** may be coupled to the secondary antenna **108**. The receiver chip **112** may include both a primary receiver (PRx) and a secondary receiver (SRx). The receiver chip **112** may output a second PRx inphase/quadrature (I/Q) signal **118** and a second SRx inphase/quadrature (I/Q) signal **120** to the baseband digital modem **122**. The

configuration of the secondary antenna **108** and the receiver chip **112** may be referred to as a secondary signal splitting carrier aggregation architecture **127**. The secondary signal splitting carrier aggregation architecture **127** is discussed in additional detail below in relation to FIG. **3**. In one configuration, the transceiver chip **110** may be located proximate to the primary antenna **106** on the wireless communication device **104** and the receiver chip **112** may be located proximate to the secondary antenna **108** on the wireless communication device **104**. In other words, the transceiver chip **110** and the receiver chip **112** may not be proximate to each other.

In general, the secondary signal splitting carrier aggregation architecture **127** may split the received signal into the second PRx inphase/quadrature (I/Q) signal **118** using a low noise amplifier (LNA) in the primary receiver (PRx) and the second SRx inphase/quadrature (I/Q) signal **120** using a routing between a first low noise amplifier (LNA) in the primary receiver (PRx) and a second low noise amplifier (LNA) in the secondary receiver (SRx) of the receiver chip **112**. There may be many different ways to split the signals. In one configuration, the stage in the first low noise amplifier (LNA) may be a transconductance stage (Gm) and the stage in the second low noise amplifier (LNA) may be a cascode stage (Cas). In another configuration, the first stage may be a transconductance stage (Gm) and the second stage may be a transformer used to split the signal.

The wireless communication device **104** may use a signal splitting carrier aggregation architecture that reuses the diversity/simultaneous hybrid dual receiver (SHDR) path. Carrier aggregation may be achieved by coupling the primary receiver (PRx) signal in a chip (i.e., in the transceiver chip **110** and the receiver chip **112**) to the diversity receiver (DRx) path. One advantage of the signal splitting carrier aggregation architecture of the present systems and methods is the ability to operate using only two antennas. Because a wireless communication device **104** with less antennas is cheaper, less bulky and less complicated, a wireless communication device **104** with the minimum number of antennas may be advantageous.

The wireless communication device **104** of the present systems and methods does not require the use of a power splitter. By removing a power splitter from the wireless communication device **104**, the wireless communication device **104** may consume less power. Furthermore, the lack of a power splitter may reduce the cost of the wireless communication device **104** and free up die area. The signal splitting carrier aggregation architecture of the present systems and methods may also not require the use of external low noise amplifiers (LNAs). External low noise amplifiers (LNAs) may consume large amounts of power and increase the cost of a wireless communication device **104**. Another benefit of the signal splitting carrier aggregation architecture of the present systems and methods is the ability to operate without die-to-die signal routing. Removing die-to-die signal routing may reduce both the complexity and cost of the wireless communication device **104**. Removing die-to-die signaling may also allow for optimal placement of antennas on the wireless communication device **104**. The signal splitting carrier aggregation architecture may have four synthesizers running.

The baseband digital modem **122** may perform processing on the first PRx inphase/quadrature (I/Q) signal **114**, the second PRx inphase/quadrature (I/Q) signal **118**, the first SRx inphase/quadrature (I/Q) signal **116** and the second SRx inphase/quadrature (I/Q) signal **120**. For example, the baseband digital modem **122** may convert the signals to the digital domain using analog-to-digital converters (ADCs) and perform digital processing on the signals using digital signal processors (DSPs). The baseband digital modem **122** may then output a first carrier signal **124***a*, a second carrier signal **124***b*, a third carrier signal **124***c* and a fourth carrier signal **124***d*. A carrier signal may refer to the carrier that the signal used.

In one configuration, the first carrier signal **124***a* and the second carrier signal **124***b* may be located in the low band while the third carrier signal **124***c* and the fourth carrier signal **124***d* are located within the midband. This may be referred to as inter-band operation or Dual-Band 4-Carrier according to Rel-10. Inter-band operation is discussed in additional detail below in relation to FIG. **5** and FIG. **6** below. In another configuration, the first carrier signal **124***a*, second carrier signal **124***b*, third carrier signal **124***c* and fourth carrier signal **124***d* may all be located within a single band, such as the low band. This may be referred to as intra-band operation or Single-Band 4-Carrier in Release-10. Intra-band operation is discussed in additional detail below in relation to FIG. **7** and FIG. **8** below.

In another configuration, the wireless communication device **104** may operate in simultaneous hybrid dual receiver (SHDR) mode. In simultaneous hybrid dual receiver (SHDR) mode, only the transceiver chip **110** may be used (i.e., the receiver chip **112** may be disabled). The configuration of the transceiver chip **110** operating in inter-band simultaneous hybrid dual receiver (SHDR) mode is discussed below in relation to FIG. **9**. The configuration of the transceiver chip **110** operating in intra-band simultaneous hybrid dual receiver (SHDR) mode is discussed below in relation to FIG. **10**.

In yet another configuration, the wireless communication device **104** may operate in diversity mode. In diversity mode, both the transceiver chip **110** and the receiver chip **112** are tuned to receive the same carrier frequency. The configuration of the transceiver chip **110** operating in diversity mode is discussed below in relation to FIG. **11**. The configuration of the receiver chip **112** operating in diversity mode is discussed below in relation to FIG. **12**.

FIG. **2** is a block diagram illustrating a primary signal splitting carrier aggregation architecture **225**. The primary signal splitting carrier aggregation architecture **225** of FIG. **2** may be one configuration of the primary signal splitting carrier aggregation architecture **125** of FIG. **1**. The primary signal splitting carrier aggregation architecture **125** may include a primary antenna **206**, a low-pass high-pass diplexer **226**, a switch **228**, four duplexers **230***a-d* and a transceiver chip **210**. The primary antenna **206** may be coupled to the low-pass high-pass diplexer **226**. The low-pass high-pass diplexer **226** may bundle low band frequencies into one signal and high band (or midband) frequencies into another signal, thus allowing the primary antenna **206** to pass both low band and midband signals to the transceiver chip **210**.

The low-pass high-pass diplexer **226** may be coupled to the switch **228**. The switch **228** may have two inputs (the signal that includes the bundled low band frequencies and the signal that includes the bundled high band frequencies) and multiple outputs. In one configuration, the switch **228** may have six possible outputs to the four duplexers **230** (representing the six possible configurations of duplexer **230** pairs). The four duplexers **230** may include a first low band (LB**1**) duplexer **230***a*, a second low band (LB**2**) duplexer **230***b*, a first midband (MB**1**) duplexer **230***c* and a second midband (MB**2**) duplexer **230***d*.

As discussed above, the transceiver chip **210** may include a transmitter **232**, a primary receiver (PRx) **234** and a secondary receiver (SRx) **236**. The transmitter **232** may include two low band outputs (LB**1**_Tx and LB**2**_Tx) and two midband outputs (MB**1**_Tx and MB**2**_Tx). The first low band output

(LB1_Tx) may be coupled to the first low band (LB1) duplexer **230***a* via a power amplifier (PA) **238***a*. The second low band output (LB2_Tx) may be coupled to the second low band (LB2) duplexer **230***b* via a power amplifier **238***b*. The first midband output (MB1_Tx) may be coupled to the first midband (MB1) duplexer **230***c* via a power amplifier **238***c*. The second midband output (MB2_Tx) may be coupled to the second midband (MB2) duplexer **230***d* via a power amplifier **238***d*.

The primary receiver (PRx) **234** may include a first low band input (LB1_PRx) coupled to the first low band (LB1) duplexer **230***a*, a second low band input (LB2_PRx) coupled to the second low band (LB2) duplexer **230***b*, a first midband input (MB1_PRx) coupled to the first midband (MB1) duplexer **230***c* and a second midband input (MB2_PRx) coupled to the second midband (MB2) duplexer **230***d*. The first low band input (LB1_PRx) may be coupled to a first low band (LB1) low noise amplifier (LNA) **240***a* that includes a transconductance stage (Gm) **244***a* and a cascode stage (Cas) **246***a*. The second low band input (LB2_PRx) may be coupled to a second low band (LB2) low noise amplifier (LNA) **240***b* that includes a transconductance stage (Gm) **244***b* and a cascode stage (Cas) **246***b*. The first midband input (MB1_PRx) may be coupled to a first midband (MB1) low noise amplifier (LNA) **242***a* that includes a transconductance stage (Gm) **244***c* and a cascode stage (Cas) **246***c*. The second midband input (MB2_PRx) may be coupled to a second midband (MB2) low noise amplifier (LNA) **242***a* that includes a transconductance stage (Gm) **244***d* and a cascode stage (Cas) **246***d*.

The primary receiver (PRx) **234** may also include a downconverter (DnC) **248***a*. The downconverter (DnC) **248***a* may be coupled to the output of the first low band (LB1) low noise amplifier (LNA) **240***a*, the output of the second low band (LB2) low noise amplifier (LNA) **240***b*, the output of the first midband (MB1) low noise amplifier (LNA) **242***a* and the output of the second midband (MB2) low noise amplifier (LNA) **242***b*.

The primary receiver (PRx) **234** may include a phase locked loop (PLL) **254***a*, a voltage controlled oscillator (VCO) **252***a* and a Div stage **250***a* that are used to generate the downconverting frequency for the downconverter (DnC) **248***a*. The output of the downconverter (DnC) **248***a* may be coupled to a primary receiver (PRx) baseband filter (BBF) **256**. The primary receiver (PRx) baseband filter (BBF) **256** may then output the first PRx inphase/quadrature (I/Q) signal **214**.

The secondary receiver (SRx) **236** may include a first low band input (LB1_SRx), a second low band input (LB2_SRx), a first midband input (MB1_SRx) and a second midband input (MB2_SRx) that are disabled. The first low band input (LB1_SRx) may be coupled to a first low band (LB1) low noise amplifier (LNA) **240***c* that includes a transconductance stage (Gm) **244***e* and a cascode stage (Cas) **246***e*. The second low band input (LB2_SRx) may be coupled to a second low band (LB2) low noise amplifier (LNA) **240***d* that includes a transconductance stage (Gm) **244***f* and a cascode stage (Cas) **246***f*. The first midband input (MB1_SRx) may be coupled to a first midband (MB1) low noise amplifier (LNA) **242***c* that includes a transconductance stage (Gm) **244***g* and a cascode stage (Cas) **246***g*. The second midband input (MB2_SRx) may be coupled to a second midband (MB2) low noise amplifier (LNA) **242***d* that includes a transconductance stage (Gm) **244***h* and a cascode stage (Cas) **246***h*. In one configuration, the first low band (LB1) low noise amplifier (LNA) **240***c*, the second low band (LB2) low noise amplifier (LNA) **240***d*, the first midband (MB1) low noise amplifier (LNA) **242***c* and the second midband (MB2) low noise amplifier (LNA) **242***d* of the secondary receiver (SRx) **236** may each be disabled. However, portions within some of the low noise amplifiers (LNAs) **240***c-d*, **242***c-d* may still be used (e.g., the transconductance stage (Gm) **244** and the Cascode stage (Cas) **246**) to allow the reuse of the diversity/simultaneous hybrid dual receiver (SHDR) receiver path (i.e., for the primary signal splitting carrier aggregation architecture **225**).

The secondary receiver (SRx) **236** may also include a downconverter (DnC) **248***b*. The downconverter (DnC) **248***b* may be coupled to the output of the first low band (LB1) low noise amplifier (LNA) **240***c*, the output of the second low band (LB2) low noise amplifier (LNA) **240***d*, the output of the first midband (MB1) low noise amplifier (LNA) **242***c* and the output of the second midband (MB2) low noise amplifier (LNA) **242***d*. The secondary receiver (SRx) **236** may further include a phase locked loop (PLL) **254***b*, a voltage controlled oscillator (VCO) **252***b* and a Div stage **250***b* that are used to generate the downconverting frequency for the downconverter (DnC) **248***b*.

The output of the downconverter (DnC) **248***b* may be coupled to a secondary receiver (SRx) baseband filter (BBF) **258**. The secondary receiver (SRx) baseband filter (BBF) **258** may then output the first SRx inphase/quadrature (I/Q) signal **216**. In one configuration, the secondary receiver (SRx) **236** may not include the secondary receiver (SRx) voltage controlled oscillator (VCO) **252***b* and the phase locked loop (PLL) **254***b* or the secondary receiver (SRx) voltage controlled oscillator (VCO) **252***b* and the phase locked loop (PLL) **254***b* may be disabled. Instead, the transceiver chip **210** may pump the same voltage controlled oscillator (VCO) signal **251** used in the primary receiver (PRx) **234** to the secondary receiver (SRx) **236**.

FIG. **3** is a block diagram illustrating a secondary signal splitting carrier aggregation architecture **327**. The secondary signal splitting carrier aggregation architecture **327** of FIG. **3** may be one configuration of the secondary signal splitting carrier aggregation architecture **127** of FIG. **1**. The secondary signal splitting carrier aggregation architecture **327** may include a secondary antenna **308**, a low-pass high-pass diplexer **326**, a switch **328**, four surface acoustic wave (SAW) filters **360***a-b*, **362***a-b* and a receiver chip **312**. The secondary antenna **308** may be coupled to the low-pass high-pass diplexer **326**. The low-pass high-pass diplexer **326** may bundle low band frequencies into one signal and high band (or mid band) frequencies into another signal, thus allowing the secondary antenna **308** to pass both low band and mid band signals to the receiver chip **312**.

The low-pass high-pass diplexer **326** may be coupled to the switch **328**. The switch **328** may have two inputs (the signal that includes the bundled low band frequencies and the signal that includes the bundled high band frequencies) and multiple outputs. In one configuration, the switch **328** may have six possible outputs to the four surface acoustic wave (SAW) filters **360**, **362** (representing the four possible configurations of surface acoustic wave (SAW) filter **360**, **362** pairs). The four surface acoustic wave (SAW) filters **360**, **362** may include a first low band (LB1) surface acoustic wave (SAW) filter **360***a*, a second low band (LB2) surface acoustic wave (SAW) filter **360***b*, a first midband (MB1) surface acoustic wave (SAW) filter **362***a* and a second midband (MB2) surface acoustic wave (SAW) filter **362***b*.

The receiver chip **312** may include a primary receiver (PRx) **334** and a secondary receiver (SRx) **336**. The primary receiver (PRx) **334** may include a first low band input (LB1_PRx) coupled to the first low band (LB1) surface acoustic wave (SAW) filter **360***a*, a second low band input

(LB2_PRx) coupled to the second low band (LB2) surface acoustic wave (SAW) filter **360***b*, a first midband input (MB1_PRx) coupled to the first midband (MB1) surface acoustic wave (SAW) filter **362***a* and a second midband input (MB2_PRx) coupled to the second midband (MB2) surface acoustic wave (SAW) filter **362***b*. The first low band input (LB1_PRx) may be coupled to a first low band (LB1) low noise amplifier (LNA) **340***a* that includes a transconductance stage (Gm) **344***a* and a cascode stage (Cas) **346***a*. The second low band input (LB2_PRx) may be coupled to a second low band (LB2) low noise amplifier (LNA) **340***b* that includes a transconductance stage (Gm) **344***b* and a cascode stage (Cas) **346***b*. The first midband input (MB1_PRx) may be coupled to a first midband (MB1) low noise amplifier (LNA) **342***a* that includes a transconductance stage (Gm) **344***c* and a cascode stage (Cas) **346***c*. The second midband input (MB2_PRx) may be coupled to a second midband (MB2) low noise amplifier (LNA) **342***b* that includes a transconductance stage (Gm) **344***d* and a cascode stage (Cas) **346***d*.

The primary receiver (PRx) **334** may also include a downconverter (DnC) **348***a*. The downconverter (DnC) **348***a* may be coupled to the output of the first low band (LB1) low noise amplifier (LNA) **340***a*, the output of the second low band (LB2) low noise amplifier (LNA) **340***b*, the output of the first midband (MB1) low noise amplifier (LNA) **342***a* and the output of the second midband (MB2) low noise amplifier (LNA) **342***b*.

The primary receiver (PRx) **334** may include a phase locked loop (PLL) **354***a*, a voltage controlled oscillator (VCO) **352***a* and a Div stage **350***a* that are used to generate the downconverting frequency for the downconverter (DnC) **348***a*. The output of the downconverter (DnC) **348***a* may be coupled to a primary receiver (PRx) baseband filter (BBF) **356**. The primary receiver (PRx) baseband filter (BBF) **356** may then output the second PRx inphase/quadrature (I/Q) signal **318**.

The secondary receiver (SRx) **336** may include a first low band input (LB1_SRx), a second low band input (LB2_SRx), a first midband input (MB1_SRx) and a second midband input (MB2_SRx) that are disabled. The first low band input (LB1_SRx) may be coupled to a first low band (LB1) low noise amplifier (LNA) **340***c* that includes a transconductance stage (Gm) **344***e* and a cascode stage (Cas) **346***e*. The second low band input (LB2_SRx) may be coupled to a second low band (LB2) low noise amplifier (LNA) **340***d* that includes a transconductance stage (Gm) **344***f* and a cascode stage (Cas) **346***f*. The first midband input (MB1_SRx) may be coupled to a first midband (MB1) low noise amplifier (LNA) **342***c* that includes a transconductance stage (Gm) **344***g* and a cascode stage (Cas) **346***g*. The second midband input (MB2_SRx) may be coupled to a second midband (MB2) low noise amplifier (LNA) **342***d* that includes a transconductance stage (Gm) **344***h* and a cascode stage (Cas) **346***h*. In one configuration, the first low band (LB1) low noise amplifier (LNA) **340***c*, the second low band (LB2) low noise amplifier (LNA) **340***d*, the first midband (MB1) low noise amplifier (LNA) **342***c* and the second midband (MB2) low noise amplifier (LNA) **342***d* may each be disabled. However, portions within some of the low noise amplifiers (LNAs) **340***c-d*, **342***c-d* may still be used (e.g., the transconductance stage (Gm) **344** and the cascode stage (Cas) **346**) to allow the reuse of the diversity/simultaneous hybrid dual receiver (SHDR) receiver path (i.e., for the secondary signal splitting carrier aggregation architecture **327**).

The secondary receiver (SRx) **336** may also include a downconverter (DnC) **348***b*. The downconverter (DnC) **348***b* may be coupled to the output of the first low band (LB1) low noise amplifier (LNA) **340***c*, the output of the second low band (LB2) low noise amplifier (LNA) **340***d*, the output of the first midband (MB1) low noise amplifier (LNA) **342***c* and the output of the second midband (MB2) low noise amplifier (LNA) **342***d*. The secondary receiver (SRx) **336** may further include a phase locked loop (PLL) **354***b*, a voltage controlled oscillator (VCO) **352***b* and a Div stage **350***b* that are used to generate the downconverting frequency for the downconverter (DnC) **348***b*. The output of the downconverter (DnC) **348***b* may be coupled to a secondary receiver (SRx) baseband filter (BBF) **358**. The secondary receiver (SRx) baseband filter (BBF) **358** may then output the second SRx inphase/quadrature (I/Q) signal **320**. In one configuration, the secondary receiver (SRx) **336** may not include the secondary receiver (SRx) voltage controlled oscillator (VCO) **352***b* and the phase locked loop (PLL) **354***b* or the secondary receiver (SRx) voltage controlled oscillator (VCO) **352***b* and the phase locked loop (PLL) **354***b* may be disabled. Instead, the receiver chip **312** may pump the same voltage controlled oscillator (VCO) signal **351** used in the primary receiver (PRx) **334** to the secondary receiver (SRx) **336**.

FIG. **4** is a flow diagram of a method **400** for receiving signals using a signal splitting carrier aggregation architecture. The method **400** may be performed by a wireless communication device **104**. The wireless communication device **104** may receive **402** a first signal using a primary antenna **106**. The wireless communication device **104** may route **404** the first signal through a primary receiver (PRx) **234** on a transceiver chip **110** to obtain a first PRx inphase/quadrature (I/Q) signal **114**. The wireless communication device **104** may also route **406** the first signal through a secondary receiver (SRx) **236** on the transceiver chip **110** to obtain a first SRx inphase/quadrature (I/Q) signal **116**.

The wireless communication device **104** may receive **408** a second signal using a secondary antenna **108**. The wireless communication device **104** may route **410** the second signal through a primary receiver (PRx) **334** on a receiver chip **112** to obtain a second PRx inphase/quadrature (I/Q) signal **118**. The wireless communication device **104** may also route **412** the second signal through a secondary receiver (SRx) **336** on the receiver chip **112** to obtain a second SRx inphase/quadrature (I/Q) signal **120**.

FIG. **5** is a block diagram illustrating a primary signal splitting carrier aggregation architecture **225** in inter-band operation. The primary signal splitting carrier aggregation architecture **225** of FIG. **5** may be the primary signal splitting carrier aggregation architecture **225** of FIG. **2**. The primary antenna **206** may be used to receive a dual-band 4-carrier signal (i.e., four carriers over two separate bands). The routing **531** from the primary antenna **206** through the primary receiver (PRx) **234** to obtain the first PRx inphase/quadrature (I/Q) signal **214** is shown. The first PRx inphase/quadrature (I/Q) signal **214** may include two carriers from a first band (e.g., the low band) for this configuration.

The routing **535** from the primary antenna **206** through the secondary receiver (SRx) **236** to obtain the first SRx inphase/quadrature (I/Q) signal **216** is also shown. The first SRx inphase/quadrature (I/Q) signal **216** may include two carriers from a second band (e.g., the midband) for this configuration. The routing **535** from the primary antenna **206** through the secondary receiver (SRx) **236** to obtain the first SRx inphase/quadrature (I/Q) signal **216** may pass through a signal splitting stage **533**. The signal splitting stage **533** may allow the primary signal splitting carrier aggregation architecture **225** to reuse the diversity/simultaneous hybrid dual receiver (SHDR) receiver path. The signal splitting stage **533** may take the signal from a low noise amplifier (LNA) (e.g., the first

midband (MB1) low noise amplifier (LNA) **242***a*) in the primary receiver (PRx) **234** after the transconductance stage (Gm) **244***c* and route the signal to a stage (e.g., the cascode stage (Cas) **246***g*) of a low noise amplifier (LNA) (e.g., the first midband (MB1) low noise amplifier (LNA) **242***c*) in the secondary receiver (SRx) **236**. In another configuration (not shown), the signal splitting stage **533** may take the signal input to the first midband (MB1) low noise amplifier (LNA) **242***a* in the primary receiver (PRx) **234** and route the signal to the transconductance stage (Gm) **244***g* of the first midband (MB1) low noise amplifier (LNA) **242***c* in the secondary receiver (SRx) **236**. The signal splitting stage **533** is discussed in additional detail below in relation to FIG. **13** and FIG. **14**. The routing **529** from the transmitter **232** to the primary antenna **206** is also shown.

FIG. **6** is a block diagram illustrating a secondary signal splitting carrier aggregation architecture **327** in inter-band operation. The secondary signal splitting carrier aggregation architecture **327** of FIG. **6** may be the secondary signal splitting carrier aggregation architecture **327** of FIG. **3**. The secondary antenna **308** may be used to receive a dual-band 4-carrier signal. The routing **631** from the secondary antenna **308** through the primary receiver (PRx) **334** to obtain the second PRx inphase/quadrature (I/Q) signal **318** is shown. The second PRx inphase/quadrature (I/Q) signal **318** may include two carriers from the low band for this configuration.

The routing **637** from the secondary antenna **308** through the secondary receiver (SRx) **336** to obtain the second SRx inphase/quadrature (I/Q) signal **320** is also shown. The second SRx inphase/quadrature (I/Q) signal **320** may include two carriers from the midband for this configuration. The routing **637** from the secondary antenna **308** through the secondary receiver (SRx) **336** to obtain the second SRx inphase/quadrature (I/Q) signal **320** may pass through a signal splitting stage **633**. The signal splitting stage **633** may allow the secondary signal splitting carrier aggregation architecture **327** to reuse the diversity/simultaneous hybrid dual receiver (SHDR) receiver path. The signal splitting stage **633** may take the signal from the first midband (MB1) low noise amplifier (LNA) **342***a* in the primary receiver (PRx) **334** after the transconductance stage (Gm) **344***c* and route the signal to the cascode stage (Cas) **346***g* of the first midband (MB1) low noise amplifier (LNA) **342***c* in the secondary receiver (SRx) **336**. In another configuration (not shown), the signal splitting stage **633** may take the signal input to the first midband (MB1) low noise amplifier (LNA) **342***b* in the primary receiver (PRx) **334** and route the signal to the transconductance stage (Gm) **344***g* of the first midband (MB1) low noise amplifier (LNA) **342***c* in the secondary receiver (SRx) **336**. The signal splitting stage **633** is discussed in additional detail below in relation to FIG. **13** and FIG. **14**.

FIG. **7** is a block diagram illustrating a primary signal splitting carrier aggregation architecture **225** in intra-band operation. The primary signal splitting carrier aggregation architecture **225** of FIG. **7** may be the primary signal splitting carrier aggregation architecture **225** of FIG. **2**. In the primary signal splitting carrier aggregation architecture **225**, 6 decibels (dB) of signal loss due to signal splitting may lead to 0.2-0.5 dB NF degradation. The primary antenna **206** may be used to receive a single-band 4-carrier signal. The routing **731** from the primary antenna **206** through the primary receiver (PRx) **234** to obtain the first PRx inphase/quadrature (I/Q) signal **214** is shown. The first PRx inphase/quadrature (I/Q) signal **214** may include two carriers from the low band for this configuration.

The routing **739** from the primary antenna **206** through the secondary receiver (SRx) **236** to obtain the first SRx inphase/quadrature (I/Q) signal **216** is also shown. The first SRx inphase/quadrature (I/Q) signal **216** may include the other two carriers from the low band for this configuration. The routing **739** from the primary antenna **206** through the secondary receiver (SRx) **236** to obtain the first SRx inphase/quadrature (I/Q) signal **216** may pass through a signal splitting stage **733**. As discussed above, the signal splitting stage **733** may allow the primary signal splitting carrier aggregation architecture **225** to reuse the diversity/simultaneous hybrid dual receiver (SHDR) receiver path. The signal splitting stage **733** may take the signal from the first low band (LB1) low noise amplifier (LNA) **240***a* in the primary receiver (PRx) **234** after the transconductance stage (Gm) **244***a* and route the signal to the cascode stage (Cas) **246***e* of the first low band (LB1) low noise amplifier (LNA) **240***c* in the secondary receiver (SRx) **236**. In another configuration (not shown), the signal splitting stage **733** may take the signal input to the first low band (LB1) low noise amplifier (LNA) **240***a* in the primary receiver (PRx) **234** and route the signal to the transconductance stage (Gm) **244***e* of the first low band (LB1) low noise amplifier (LNA) **240***c* in the secondary receiver (SRx) **236**. The signal splitting stage **733** is discussed in additional detail below in relation to FIG. **13** and FIG. **14**. The routing **729** from the transmitter **232** to the primary antenna **206** is also shown.

FIG. **8** is a block diagram illustrating a secondary signal splitting carrier aggregation architecture **327** in intra-band operation. The secondary signal splitting carrier aggregation architecture **327** of FIG. **8** may be the secondary signal splitting carrier aggregation architecture **327** of FIG. **3**. The secondary antenna **308** may be used to receive a single-band 4-carrier signal. The routing **831** from the secondary antenna **308** through the primary receiver (PRx) **336** to obtain the second PRx inphase/quadrature (I/Q) signal **318** is shown. The second PRx inphase/quadrature (I/Q) signal **318** may include two carriers from the low band for this configuration.

The routing **881** from the secondary antenna **308** through the secondary receiver (SRx) **336** to obtain the second SRx inphase/quadrature (I/Q) signal **320** is also shown. The second SRx inphase/quadrature (I/Q) signal **320** may include the other two carriers from the low band for this configuration. The routing **881** from the secondary antenna **308** through the secondary receiver (SRx) **336** to obtain the second SRx inphase/quadrature (I/Q) signal **320** may pass through a signal splitting stage **833**. As discussed above, the signal splitting stage **833** may allow the secondary signal splitting carrier aggregation architecture **327** to reuse the diversity/simultaneous hybrid dual receiver (SHDR) receiver path. In another configuration (not shown), the signal splitting stage **833** may take the signal input to the first low band (LB1) low noise amplifier (LNA) **340***a* in the primary receiver (PRx) **334** and route the signal to the transconductance stage (Gm) **344***e* of the first low band (LB1) low noise amplifier (LNA) **340***c* in the secondary receiver (SRx) **336**. The signal splitting stage **833** is discussed in additional detail below in relation to FIG. **13** and FIG. **14**.

FIG. **9** is a block diagram illustrating a primary signal splitting carrier aggregation architecture **225** operating in inter-band simultaneous hybrid dual receiver (SHDR) mode. The primary signal splitting carrier aggregation architecture **225** of FIG. **9** may be the primary signal splitting carrier aggregation architecture **225** of FIG. **2**. The primary antenna **206** may be used to receive signals on a low band carrier and a midband carrier. The routing **931** from the primary antenna **206** through the primary receiver (PRx) **234** to obtain the first PRx inphase/quadrature (I/Q) signal **214** is shown. The first

PRx inphase/quadrature (I/Q) signal **214** may include the low band carrier for this configuration.

The routing **943** from the primary antenna **206** through the secondary receiver (SRx) **236** to obtain the first SRx inphase/quadrature (I/Q) signal **216** is also shown. The first SRx inphase/quadrature (I/Q) signal **216** may include the midband carrier for this configuration. The routing **943** from the primary antenna **206** through the secondary receiver (SRx) **236** to obtain the first SRx inphase/quadrature (I/Q) signal **216** may pass through a signal splitting stage **933**. The signal splitting stage **933** may take the signal from the first midband (MB**1**) low noise amplifier (LNA) **242***a* in the primary receiver (PRx) **234** after the transconductance stage (Gm) **244***c* and route the signal to the cascode stage (Cas) **246***g* of the first midband (MB**1**) low noise amplifier (LNA) **242***c* in the secondary receiver (SRx) **236**. In another configuration (not shown), the signal splitting stage **933** may take the signal input to the first midband (MB**1**) low noise amplifier (LNA) **242***a* in the primary receiver (PRx) **234** and route the signal to the transconductance stage (Gm) **244***g* of the first midband (MB**1**) low noise amplifier (LNA) **242***c* in the secondary receiver (SRx) **236**. The signal splitting stage **933** is discussed in additional detail below in relation to FIG. **13** and FIG. **14**. The routing **929** from the transmitter **232** to the primary antenna **206** is also shown.

FIG. **10** is a block diagram illustrating a primary signal splitting carrier aggregation architecture **225** operating in intra-band simultaneous hybrid dual receiver (SHDR) mode. The primary signal splitting carrier aggregation architecture **225** of FIG. **10** may be the primary signal splitting carrier aggregation architecture **225** of FIG. **2**. The primary antenna **206** may be used to receive signals on two low band carriers. The routing **1031** from the primary antenna **206** through the primary receiver (PRx) **234** to obtain the first PRx inphase/quadrature (I/Q) signal **214** is shown. The first PRx inphase/quadrature (I/Q) signal **214** may include one of the low band carriers for this configuration.

The routing **1045** from the primary antenna **206** through the secondary receiver (SRx) **236** to obtain the first SRx inphase/quadrature (I/Q) signal **216** is also shown. The first SRx inphase/quadrature (I/Q) signal **216** may include the other low band carrier for this configuration. The routing **1045** from the primary antenna **206** through the secondary receiver (SRx) **236** to obtain the first SRx inphase/quadrature (I/Q) signal **216** may pass through a signal splitting stage **1033**. The signal splitting stage **1033** may take the signal from the first low band (LB**1**) low noise amplifier (LNA) **240***a* in the primary receiver (PRx) **234** after the transconductance stage (Gm) **244***a* and route the signal to the cascode stage (Cas) **246***e* of the first low band (LB**1**) low noise amplifier (LNA) **240***c* in the secondary receiver (SRx) **236**. In another configuration (not shown), the signal splitting stage **1033** may take the signal input to the first low band (LB**1**) low noise amplifier (LNA) **240***a* in the primary receiver (PRx) **234** and route the signal to the transconductance stage (Gm) **244***e* of the first low band (LB**1**) low noise amplifier (LNA) **240***c* in the secondary receiver (SRx) **236**. The signal splitting stage **1033** is discussed in additional detail below in relation to FIG. **13** and FIG. **14**. The routing **1029** from the transmitter **232** to the primary antenna **206** is also shown.

FIG. **11** is a block diagram illustrating a primary signal splitting carrier aggregation architecture **225** operating in diversity mode. The primary signal splitting carrier aggregation architecture **225** of FIG. **10** may be the primary signal splitting carrier aggregation architecture **225** of FIG. **2**. The primary antenna **206** may be used to receive signals on a low band carrier. The routing **1131** from the primary antenna **206** through the primary receiver (PRx) **234** to obtain the first PRx inphase/quadrature (I/Q) signal **214** is shown. The first PRx inphase/quadrature (I/Q) signal **214** may include the low band carrier for this configuration. The routing **1129** from the transmitter **232** to the primary antenna **206** is also shown. In diversity mode, no routing is used through the secondary receiver (SRx) **236**. However, in diversity mode, two synthesizers may need to be run instead of one; this may lead to higher power consumption in diversity mode.

FIG. **12** is a block diagram illustrating a secondary signal splitting carrier aggregation architecture **327** operating in diversity mode. The secondary signal splitting carrier aggregation architecture **327** of FIG. **12** may be the secondary signal splitting carrier aggregation architecture **327** of FIG. **3**. The secondary antenna **308** may be used to receive signals on a low band carrier. The routing **1231** from the secondary antenna **308** through the primary receiver (PRx) **334** to obtain the second PRx inphase/quadrature (I/Q) signal **318** is shown. The second PRx inphase/quadrature (I/Q) signal **318** may include the low band carrier for this configuration. In diversity mode, no routing is used through the secondary receiver (SRx) **336**.

FIG. **13** is a block diagram illustrating a signal splitting stage **1333**. The signal splitting stage **1333** of FIG. **13** may be one configuration of the signal splitting stage **533** in FIG. **5**, the signal splitting stage **633** in FIG. **6**, the signal splitting stage **733** in FIG. **7**, the signal splitting stage **833** in FIG. **8**, the signal splitting stage **933** in FIG. **9** and the signal splitting stage **1033** in FIG. **10**. The signal splitting stage **1333** may include a first transconductance stage (Gm) **1344***a*, a first cascode stage (Cas) **1346***a*, a second transconductance stage (Gm) **1344***b*, a second cascode stage (Cas) **1346***b* and passive mixers **1348***a-d*. The first transconductance stage (Gm) **1344***a* and the first cascode stage (Cas) **1346***a* may be part of a low noise amplifier (LNA) on a primary receiver (PRx) while the second transconductance stage (Gm) **1344***b* and the second cascode stage (Cas) **1346***b* may be part of a low noise amplifier (LNA) on a secondary receiver (SRx).

The outputs of the first transconductance stage (Gm) **1344***a* may be input to the first cascode stage (Cas) **1346***a*. The outputs of the first cascode stage (Cas) **1346***a* may then be mixed via the passive mixers **1348***a-b* to obtain the primary receiver (PRx) inphase signal PRx_I_CH **1360***a-b* and the primary receiver (PRx) quadrature signal PRx_Q_CH **1360***c-d* of a primary receiver (PRx) signal. In the signal splitting stage **1333**, the signal splitting occurs after the first transconductance stage (Gm) **1344***a*. Thus, the outputs of the first transconductance stage (Gm) **1344***a* may be input to the inputs of the second cascode stage (Cas) **1346***b*. The outputs of the second cascode stage (Cas) **1346***b* may then be mixed via the passive mixers **1348***c-d* to obtain the secondary receiver (SRx) inphase signal SRx_I_CH **1360***e-f* and the secondary receiver (SRx) quadrature signal SRx_Q_CH **1360***g-h* of a secondary receiver (SRx) signal.

Switches may be used between the primary receiver (PRx) and the secondary receiver (SRx) to allow a clean standalone operation. The low noise amplifier (LNA) topology may drive the signal splitting sensing point.

FIG. **14** is a block diagram illustrating another signal splitting stage. The signal splitting stage **1433** of FIG. **14** may be one configuration of the signal splitting stage **533** in FIG. **5**, the signal splitting stage **633** in FIG. **6**, the signal splitting stage **733** in FIG. **7**, the signal splitting stage **833** in FIG. **8**, the signal splitting stage **933** in FIG. **9** and the signal splitting stage **1033** in FIG. **10**. The signal splitting stage **1433** may include a set of first stage amplifiers **1444**, second stage amplifiers **1446** and passive mixers **1448***a-d*. The first stage

amplifiers **1444** of FIG. **14** may be one configuration of the transconductance stages (GM) **244**, **344** of FIG. **2** and FIG. **3**. In one configuration, the second stage amplifiers **1446** may be cascode stages (such as the cascode stages **246** illustrated in FIG. **2** and the cascode stages **346** illustrated in FIG. **3**). The upper first stage amplifier **1444** and the upper second stage amplifier **1446** may be part of a low noise amplifier (LNA) on a primary receiver (PRx) while the lower first stage amplifier **1444** and the lower second stage amplifier **1446** may be part of a low noise amplifier (LNA) on a secondary receiver (SRx).

The outputs of the upper first stage amplifier **1444** may be input to the upper second stage amplifier **1446**. The outputs of the upper second stage amplifier **1446** may then be mixed via the passive mixers **1448***a-b* to obtain the primary receiver (PRx) inphase signal PRx_I_CH **1460***a-b* and the primary receiver (PRx) quadrature signal PRx_Q_CH **1460***c-d* of a primary receiver (PRx) signal. In the signal splitting stage **1433**, the signal splitting occurs after the upper second stage amplifier **1446**. Thus, the outputs of the upper second stage amplifier **1446** may be input to the passive mixers **1448***c-d* of the secondary receiver (SRx) to obtain the secondary receiver (SRx) inphase signal SRx_I_CH **1460***e-f* and the secondary receiver (SRx) quadrature signal SRx_Q_CH **1460***g-h* of a secondary receiver (SRx) signal.

FIG. **15** illustrates certain components that may be included within a wireless communication device **2104**. The wireless communication device **2104** may be an access terminal, a mobile station, a user equipment (UE), etc. The wireless communication device **2104** includes a processor **2103**. The processor **2103** may be a general purpose single- or multi-chip microprocessor (e.g., an ARM), a special purpose microprocessor (e.g., a digital signal processor (DSP)), a microcontroller, a programmable gate array, etc. The processor **2103** may be referred to as a central processing unit (CPU). Although just a single processor **2103** is shown in the wireless communication device **2104** of FIG. **15**, in an alternative configuration, a combination of processors (e.g., an ARM and DSP) could be used.

The wireless communication device **2104** also includes memory **2105**. The memory **2105** may be any electronic component capable of storing electronic information. The memory **2105** may be embodied as random access memory (RAM), read-only memory (ROM), magnetic disk storage media, optical storage media, flash memory devices in RAM, on-board memory included with the processor, EPROM memory, EEPROM memory, registers and so forth, including combinations thereof.

Data **2107***a* and instructions **2109***a* may be stored in the memory **2105**. The instructions **2109***a* may be executable by the processor **2103** to implement the methods disclosed herein. Executing the instructions **2109***a* may involve the use of the data **2107***a* that is stored in the memory **2105**. When the processor **2103** executes the instructions **2109**, various portions of the instructions **2109***b* may be loaded onto the processor **2103**, and various pieces of data **2107***b* may be loaded onto the processor **2103**.

The wireless communication device **2104** may also include a transmitter **2111** and a receiver **2113** to allow transmission and reception of signals to and from the wireless communication device **2104** via a first antenna **2117***a* and a second antenna **2117***b*. The transmitter **2111** and receiver **2113** may be collectively referred to as a transceiver **2115**. The wireless communication device **2104** may also include (not shown) multiple transmitters, additional antennas, multiple receivers and/or multiple transceivers.

The wireless communication device **2104** may include a digital signal processor (DSP) **2121**. The wireless communication device **2104** may also include a communications interface **2123**. The communications interface **2123** may allow a user to interact with the wireless communication device **2104**.

The various components of the wireless communication device **2104** may be coupled together by one or more buses, which may include a power bus, a control signal bus, a status signal bus, a data bus, etc. For the sake of clarity, the various buses are illustrated in FIG. **15** as a bus system **2119**.

The term "determining" encompasses a wide variety of actions and, therefore, "determining" can include calculating, computing, processing, deriving, investigating, looking up (e.g., looking up in a table, a database or another data structure), ascertaining and the like. Also, "determining" can include receiving (e.g., receiving information), accessing (e.g., accessing data in a memory) and the like. Also, "determining" can include resolving, selecting, choosing, establishing and the like.

The phrase "based on" does not mean "based only on," unless expressly specified otherwise. In other words, the phrase "based on" describes both "based only on" and "based at least on."

The term "processor" should be interpreted broadly to encompass a general purpose processor, a central processing unit (CPU), a microprocessor, a digital signal processor (DSP), a controller, a microcontroller, a state machine and so forth. Under some circumstances, a "processor" may refer to an application specific integrated circuit (ASIC), a programmable logic device (PLD), a field programmable gate array (FPGA), etc. The term "processor" may refer to a combination of processing devices, e.g., a combination of a DSP and a microprocessor, a plurality of microprocessors, one or more microprocessors in conjunction with a DSP core, or any other such configuration.

The term "memory" should be interpreted broadly to encompass any electronic component capable of storing electronic information. The term memory may refer to various types of processor-readable media such as random access memory (RAM), read-only memory (ROM), non-volatile random access memory (NVRAM), programmable read-only memory (PROM), erasable programmable read-only memory (EPROM), electrically erasable PROM (EEPROM), flash memory, magnetic or optical data storage, registers, etc. Memory is said to be in electronic communication with a processor if the processor can read information from and/or write information to the memory. Memory that is integral to a processor is in electronic communication with the processor.

The terms "instructions" and "code" should be interpreted broadly to include any type of computer-readable statement (s). For example, the terms "instructions" and "code" may refer to one or more programs, routines, sub-routines, functions, procedures, etc. "Instructions" and "code" may comprise a single computer-readable statement or many computer-readable statements.

The functions described herein may be implemented in hardware, software, firmware, or any combination thereof. If implemented in software, the functions may be stored as one or more instructions on a computer-readable medium. The terms "computer-readable medium" or "computer-program product" refers to any available medium that can be accessed by a computer. By way of example, and not limitation, a computer-readable medium may comprise RAM, ROM, EEPROM, CD-ROM or other optical disk storage, magnetic disk storage or other magnetic storage devices, or any other medium that can be used to carry or store desired program code in the form of instructions or data structures and that can be accessed by a computer. Disk and disc, as used herein, includes compact disc (CD), laser disc, optical disc, digital

versatile disc (DVD), floppy disk and Blu-ray® disc where disks usually reproduce data magnetically, while discs reproduce data optically with lasers.

Software or instructions may also be transmitted over a transmission medium. For example, if the software is transmitted from a website, server, or other remote source using a coaxial cable, fiber optic cable, twisted pair, digital subscriber line (DSL), or wireless technologies such as infrared, radio and microwave, then the coaxial cable, fiber optic cable, twisted pair, DSL, or wireless technologies such as infrared, radio and microwave are included in the definition of transmission medium.

The methods disclosed herein comprise one or more steps or actions for achieving the described method. The method steps and/or actions may be interchanged with one another without departing from the scope of the claims. In other words, unless a specific order of steps or actions is required for proper operation of the method that is being described, the order and/or use of specific steps and/or actions may be modified without departing from the scope of the claims.

Further, it should be appreciated that modules and/or other appropriate means for performing the methods and techniques described herein, such as those illustrated by FIG. **4**, can be downloaded and/or otherwise obtained by a device. For example, a device may be coupled to a server to facilitate the transfer of means for performing the methods described herein. Alternatively, various methods described herein can be provided via a storage means (e.g., random access memory (RAM), read-only memory (ROM), a physical storage medium such as a compact disc (CD) or floppy disk, etc.), such that a device may obtain the various methods upon coupling or providing the storage means to the device. Moreover, any other suitable technique for providing the methods and techniques described herein to a device can be utilized.

It is to be understood that the claims are not limited to the precise configuration and components illustrated above. Various modifications, changes and variations may be made in the arrangement, operation and details of the systems, methods and apparatus described herein without departing from the scope of the claims.

What is claimed is:

1. A wireless communication device configured for receiving a multiple carrier signal, comprising:

a primary signal splitting carrier aggregation architecture comprising:

a primary antenna;

a transceiver chip comprising a first primary receiver and a first secondary receiver, the transceiver chip configured for both carrier aggregation operation and diversity/simultaneous hybrid dual receiver operation; and

routing configured to route a signal split from a signal received from the primary antenna into a first primary signal and a first secondary signal, the routing further configured to route the first secondary signal to the first secondary receiver from a path within the first primary receiver; and

a secondary signal splitting carrier aggregation architecture comprising:

a secondary antenna;

a receiver chip comprising a second primary receiver and a second secondary receiver, the receiver chip configured for both carrier aggregation operation and diversity/simultaneous hybrid dual receiver operation:

routing configured to route a signal received from the secondary antenna to the second primary receiver and the second secondary receiver.

2. The wireless communication device of claim **1**, wherein the primary signal splitting carrier aggregation architecture and the secondary signal splitting carrier aggregation architecture do not require four antennas, a power splitter, an external low noise amplifier or die-to-die signal routing.

3. The wireless communication device of claim **1**, wherein the transceiver chip comprises:

a transmitter;

wherein each receiver comprises multiple low noise amplifiers for a first band and multiple low noise amplifiers for a second band, and wherein each low noise amplifier comprises a first stage amplifier and a second stage amplifier.

4. The wireless communication device of claim **3**, wherein the first stage amplifier is a transconductance stage, and wherein the second stage amplifier is a cascode stage.

5. The wireless communication device of claim **3**, wherein the first band is a low band and the second band is a mid band.

6. The wireless communication device of claim **3**, wherein the first band is a low band and the second band is a high band.

7. The wireless communication device of claim **3**, wherein the first band is a mid band and the second band is a high band.

8. The wireless communication device of claim **3**, wherein:

the routing configured to route a signal split from a signal received from the primary antenna further comprises:

a first routing from the primary antenna through the first primary receiver to obtain the first primary signal comprising a first primary inphase/quadrature signal; and

a second routing from the first primary receiver through the first secondary receiver to obtain the first secondary signal comprising a first secondary inphase/quadrature signal; and

the routing configured to route a signal received from the secondary antenna further comprises:

a third routing is used from the secondary antenna through the second primary receiver to obtain a second primary inphase/quadrature signal; and

a fourth routing is used from the secondary antenna through the second secondary receiver to obtain a second secondary inphase/quadrature signal.

9. The wireless communication device of claim **8**, wherein the primary signal splitting carrier aggregation architecture and the secondary signal splitting carrier aggregation architecture are in inter-band operation, wherein the second routing passes through a first signal splitting stage, and wherein the fourth routing passes through a second signal splitting stage.

10. The wireless communication device of claim **9**, wherein the first signal splitting stage routes a signal output from a first stage amplifier in a first band low noise amplifier of the first primary receiver to a second stage amplifier in a second band low noise amplifier of the first secondary receiver.

11. The wireless communication device of claim **9**, wherein the second signal splitting stage routes a signal output from a first stage amplifier in a first band low noise amplifier of the second primary receiver to a second stage amplifier in a second band low noise amplifier of the second secondary receiver.

12. The wireless communication device of claim **9**, wherein the first signal splitting stage routes a signal output from a second stage amplifier in a first band low noise amplifier of the first primary receiver to a mixer in the first secondary receiver.

13. The wireless communication device of claim **9**, wherein the second signal splitting stage routes a signal out-

put from a second stage amplifier in a first band low noise amplifier of the second primary receiver to a mixer in the second secondary receiver.

14. The wireless communication device of claim **8**, wherein the primary signal splitting carrier aggregation architecture and the secondary signal splitting carrier aggregation architecture are in intra-band operation, wherein the second routing passes through a first signal splitting stage, and wherein the fourth routing passes through a second signal splitting stage.

15. The wireless communication device of claim **14**, wherein the first signal splitting stage splits a signal output from a first stage amplifier in a first band low noise amplifier of the first primary receiver, routes the signal to a second stage amplifier in the first band low noise amplifier of the first primary receiver and routes the signal to a second stage amplifier in a second band low noise amplifier of the first secondary receiver.

16. The wireless communication device of claim **14**, wherein the second signal splitting stage splits a signal output from a first stage amplifier in a first band low noise amplifier of the second primary receiver, routes the signal to a second stage amplifier in the first band low noise amplifier of the second primary receiver and routes the signal to a second stage amplifier in a second band low noise amplifier of the second secondary receiver.

17. The wireless communication device of claim **14**, wherein the first signal splitting stage splits a signal output from a second stage amplifier in a first band low noise amplifier of the first primary receiver, routes the signal to a first mixer of the first primary receiver and routes the signal to a second mixer of the second primary receiver.

18. The wireless communication device of claim **14**, wherein the second signal splitting stage splits a signal output from a second stage amplifier in a first band low noise amplifier of the second primary receiver, routes the signal to a first mixer of the second primary receiver and routes the signal to a second mixer of the second primary receiver.

19. A method for receiving a multiple carrier signal using a primary signal splitting carrier aggregation architecture and a secondary signal splitting carrier aggregation architecture, comprising:

receiving a first signal using a primary antenna;

routing the first signal through a first primary receiver on a transceiver chip in the primary signal splitting carrier aggregation architecture to obtain a first primary inphase/quadrature signal, wherein the transceiver chip is configured for both carrier aggregation operation and diversity/simultaneous hybrid dual receiver operation;

routing the first signal through a path within the first primary receiver to a first secondary receiver on the transceiver chip to obtain a first secondary inphase/quadrature signal;

receiving a second signal using a secondary antenna;

routing the second signal through a second primary receiver on a receiver chip in the secondary signal splitting carrier aggregation architecture to obtain a second primary inphase/quadrature signal, wherein the receiver chip is configured for both carrier aggregation operation and diversity/simultaneous hybrid dual receiver operation; and

routing the second signal through a path within the second primary receiver to a second secondary receiver on the receiver chip to obtain a second secondary inphase/quadrature signal.

20. The method of claim **19**, wherein the primary signal splitting carrier aggregation architecture and the secondary signal splitting carrier aggregation architecture do not require four antennas, a power splitter, an external low noise amplifier or die-to-die signal routing.

21. The method of claim **19**, wherein each receiver comprises multiple low noise amplifiers for a first band and multiple low noise amplifiers for a second band, and wherein each low noise amplifier comprises a first stage amplifier and a second stage amplifier.

22. The method of claim **21**, wherein the first stage amplifier is a transconductance stage, and wherein the second stage amplifier is a cascode stage.

23. The method of claim **21**, wherein the first band is a low band and the second band is a mid band.

24. The method of claim **21**, wherein the first band is a low band and the second band is a high band.

25. The method of claim **21**, wherein the first band is a mid band and the second band is a high band.

26. The method of claim **21**, wherein a first routing is used from the primary antenna through the first primary receiver to obtain the first primary inphase/quadrature signal, wherein the path within the first primary receiver comprises a second routing from the primary antenna through the first secondary receiver to obtain the first secondary inphase/quadrature signal, wherein a third routing is used from the secondary antenna through the second primary receiver to obtain the second primary inphase/quadrature signal, and wherein the path within the second primary receiver comprises a fourth routing from the secondary antenna through the second secondary receiver to obtain a second secondary inphase/quadrature signal.

27. The method of claim **26**, wherein the primary signal splitting carrier aggregation architecture and the secondary signal splitting carrier aggregation architecture are in inter-band operation, wherein the second routing passes through a first signal splitting stage, and wherein the fourth routing passes through a second signal splitting stage.

28. The method of claim **27**, wherein the first signal splitting stage routes a signal output from a first stage amplifier in a first band low noise amplifier of the first primary receiver to a second stage amplifier in a second band low noise amplifier of the first secondary receiver.

29. The method of claim **27**, wherein the second signal splitting stage routes a signal output from a first stage amplifier in a first band low noise amplifier of the second primary receiver to a second stage amplifier in a second band low noise amplifier of the second secondary receiver.

30. The method of claim **27**, wherein the first signal splitting stage routes a signal output from a second stage amplifier in a first band low noise amplifier of the first primary receiver to a mixer in the first secondary receiver.

31. The method of claim **27**, wherein the second signal splitting stage routes a signal output from a second stage amplifier in a first band low noise amplifier of the second primary receiver to a mixer in the second secondary receiver.

32. The method of claim **26**, wherein the primary signal splitting carrier aggregation architecture and the secondary signal splitting carrier aggregation architecture are in intra-band operation, wherein the second routing passes through a first signal splitting stage, and wherein the fourth routing passes through a second signal splitting stage.

33. The method of claim **32**, wherein the first signal splitting stage splits a signal output from a first stage amplifier in a first band low noise amplifier of the first primary receiver, routes the signal to a second stage amplifier in the first band low noise amplifier of the first primary receiver and routes the signal to a second stage amplifier in a second band low noise amplifier of the first secondary receiver.

34. The method of claim 32, wherein the second signal splitting stage splits a signal output from a first stage amplifier in a first band low noise amplifier of the second primary receiver, routes the signal to a second stage amplifier in the first band low noise amplifier of the second primary receiver and routes the signal to a second stage amplifier in a second band low noise amplifier of the second secondary receiver.

35. The method of claim 32, wherein the first signal splitting stage splits a signal output from a second stage amplifier in a first band low noise amplifier of the first primary receiver, routes the signal to a first mixer of the first primary receiver and routes the signal to a second mixer of the second primary receiver.

36. The method of claim 32, wherein the second signal splitting stage splits a signal output from a second stage amplifier in a first band low noise amplifier of the second primary receiver, routes the signal to a first mixer of the second primary receiver and routes the signal to a second mixer of the second primary receiver.

37. An apparatus for receiving a multiple carrier signal using a primary signal splitting carrier aggregation architecture and a secondary signal splitting carrier aggregation architecture, comprising:

means for receiving a first signal using a primary antenna;

means for routing the first signal through a first primary receiver on a transceiver chip in the primary signal splitting carrier aggregation architecture to obtain a first primary inphase/quadrature signal, wherein the transceiver chip is configured for both carrier aggregation operation and diversity/simultaneous hybrid dual receiver operation;

means for routing the first signal through a path within the first primary receiver to a first secondary receiver on the transceiver chip to obtain a first secondary inphase/quadrature signal;

means for receiving a second signal using a secondary antenna;

means for routing the second signal through a second primary receiver on a receiver chip in the secondary signal splitting carrier aggregation architecture to obtain a second primary inphase/quadrature signal, wherein the receiver chip is configured for both carrier aggregation operation and diversity/simultaneous hybrid dual receiver operation; and

means for routing the second signal through a path within the second primary receiver to a second secondary receiver on the receiver chip to obtain a second secondary inphase/quadrature signal.

38. The apparatus of claim 37, wherein the primary signal splitting carrier aggregation architecture and the secondary signal splitting carrier aggregation architecture do not require four antennas, a power splitter, an external low noise amplifier or die-to-die signal routing.

39. The apparatus of claim 37, wherein each receiver comprises multiple low noise amplifiers for a first band and multiple low noise amplifiers for a second band, and wherein each low noise amplifier comprises a first stage and a second stage.

40. The apparatus of claim 39, wherein a first routing is used from the primary antenna through the first primary receiver to obtain the first primary inphase/quadrature signal, wherein the path within the first primary receiver comprises a second routing from the primary antenna through the first secondary receiver to obtain the first secondary inphase/quadrature signal, wherein a third routing is used from the secondary antenna through the second primary receiver to obtain the second primary inphase/quadrature signal, and wherein the path within the secondary primary receiver comprises a fourth routing from the secondary antenna through the second secondary receiver to obtain a second secondary inphase/quadrature signal.

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